



# A7600C&A7608SA-H Hardware Design(LINUX)

LTE Module

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# 1 Introduction

This document describes the electronic specifications, RF specifications, interfaces, mechanical characteristics and testing results of the SIMCom module. With the help of this document and other software application notes/user guides, users can understand and use module to design and develop applications quickly.

## 1.1 Product Outline

Aimed at the global market, the module support GSM, WCDMA, LTE-TDD and LTE-FDD. Users can choose the module according to the wireless network configuration. The supported radio frequency bands are described in the following table.

**Table 1: Module Frequency Bands**

Standard	Frequency bands	Module		
		A7602E-H	A7608SA-H	A7600C
GSM	850MHz		✓	
	900MHz	✓	✓	✓
	1800MHz	✓	✓	✓
	1900MHz		✓	
WCDMA	BAND1	✓	✓	✓
	BAND2		✓	
	BAND5		✓	
	BAND8	✓	✓	✓
LTE-FDD	LTE-FDD B1	✓	✓	✓
	LTE-FDD B2		✓	
	LTE-FDD B3	✓	✓	✓
	LTE-FDD B4		✓	
	LTE-FDD B5	✓	✓	✓
	LTE-FDD B7	✓	✓	
	LTE-FDD B8	✓	✓	✓
	LTE-FDD B20	✓	✓	
	LTE-FDD B28		✓	
	LTE-FDD B66		✓	
LTE-TDD	LTE TDD B34			✓
	LTE TDD B38	✓	✓	✓

	LTE TDD B39			✓
	LTE TDD B40	✓	✓	✓
	LTE TDD B41	✓	✓	✓
<b>Category</b>	/	CAT4	CAT4	CAT4
<b>GNSS</b>	/	Optional	Optional	Optional
<b>Aux ANT</b>	/	Optional	Optional	Optional
<b>Main ANT</b>	/	Optional	Optional	Optional

With a small physical dimension of 30\*30\*2.5 mm and with the functions integrated, the module can meet almost any space requirement in users' applications, such as smart phone, PDA, industrial handheld, machine-to-machine and vehicle application, etc.

## 1.2 Hardware Interfaces Overview

The interfaces are described in detail in the next chapter include:

- Power Supply
- USB2.0 Interface
- UART Interfaces
- MMC/SD Interface
- SDIO Interface
- USIM Interface
- GPIOs
- ADC
- Two channels LDO Power Output
- PCM Interface
- SPI Interface
- I2C Interface
- RMII Interface
- PCIe Interface\*
- Analog Audio Interface

## 1.3 Hardware Block Diagram

The block diagram of the module is shown in the figure below.

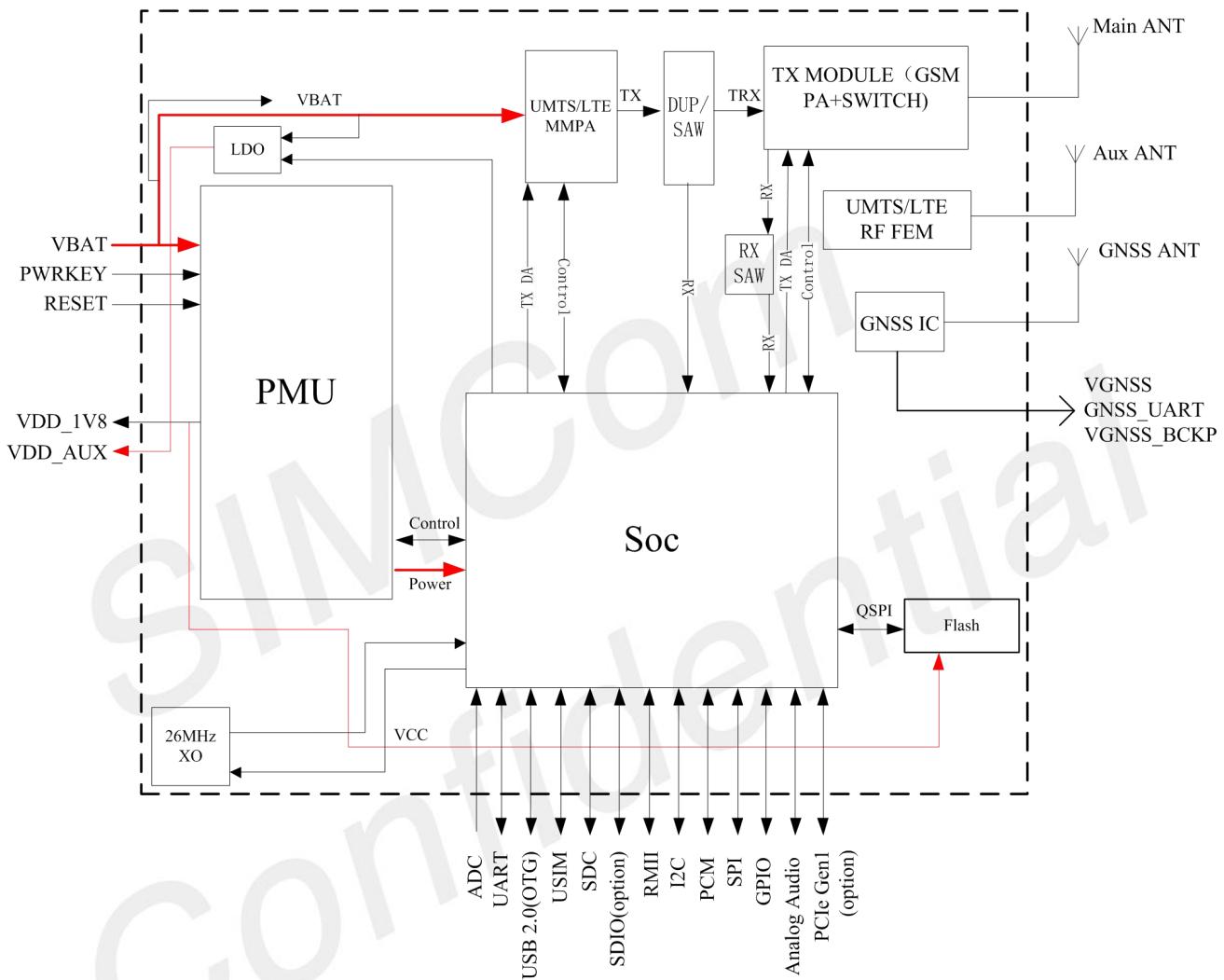


Figure 1: Module Block Diagram

## 1.4 Functional Overview

Table 2: General Features

Feature	Implementation
<b>Power supply</b>	Single supply voltage 3.4 ~ 4.2 V, recommend 3.8 V.
<b>Power saving</b>	Current in sleep mode : <5 mA
<b>Radio frequency bands</b>	Please refer to the table 1  GSM/GPRS power class: --GSM850: 4 (2W) --EGSM900: 4 (2W) --DCS1800: 1 (1W) --PCS1900: 1 (1W)  EDGE power class: --GSM850: E2 (0.5W) --EGSM900: E2 (0.5W) --DCS1800: E1 (0.4W) --PCS1900: E1 (0.4W)  UMTS power class: --WCDMA :3 (0.25W)
<b>Transmitting power</b>	LTE power class: 3 (0.25W)  GPRS multi-slot class 12  EDGE multi-slot class 12  UMTS R99 speed: 384 kbps DL/UL  HSPA+: 5.76 Mbps(UL), 42 Mbps(DL)  HSDPA/HSUPA: 2.2 Mbps(UL), 2.8 Mbps(DL)  LTE-FDD CAT4 : 150 Mbps (DL), 50 Mbps (UL)  LTE-TDD CAT4 : 130 Mbps (DL), 35 Mbps (UL)
<b>Data Transmission Throughput</b>	GSM/UMTS/LTE main antenna.
<b>Antenna</b>	UMTS/LTE auxiliary antenna  GNSS antenna
<b>GNSS</b>	GNSS engine (GPS,GLONASS and BD)  Protocol: NMEA
<b>SMS</b>	MT, MO, CB, Text and PDU mode  SMS storage: USIM card or ME(default)  Transmission of SMS alternatively over CS or PS.
<b>USIM interface</b>	Support identity card: 1.8 V / 3 V
<b>USIM application toolkit</b>	Support SAT class 3, GSM 11.14 Release 98  Support USAT
<b>Phonebook management</b>	Support phonebook types: DC,MC,RC,SM,ME,FD,ON,LD,EN  Support PCM interface
<b>Audio feature</b>	Only support PCM master mode and short frame sync, 16-bit linear data formats

	Support analog audio interface
<b>UART interfaces</b>	<p><b>MAIN UART:</b></p> <p>A full modem serial port by default            Baud rate: 9600 bps to 3.6Mbps(default:115200 bps)            Can be used as the AT commands or data stream channel            Support RTS/CTS hardware handshake            Multiplex ability according to GSM 07.10 Multiplexer Protocol</p> <p><b>UART2:</b></p> <p>Receive GNSS data</p> <p><b>Debug UART:</b></p> <p>Used for Software console and log output            Baud rate: 9600 bps to 3.6 Mbps(default:115200 bps)</p> <p><b>GNSS UART:</b></p> <p>GNSS UART communication interface;            Baud rate: 9600 bps or 115200 bps(default:9600 bps)</p>
<b>eMMC/SD</b>	Support eMMC and SD Cards with 2.85 V on SD port
<b>SDIO</b>	Support SDIO with 1.8 V only on SDIO port
<b>USB</b>	USB2.0 high speed interface
<b>PCIe</b>	Support PCIe Gen1 Host mode for WiFi connection*(in developing) Single Lane
<b>RMII</b>	Support 100M/1000M Ethernet Support 3.3v or 1.8v phy
<b>Firmware upgrade</b>	Firmware upgrade over USB interface
<b>Physical characteristics</b>	Size:30*30*2.5 mm Weight:5.7 g
<b>Temperature range</b>	Normal operation temperature: -30 °C to +80 °C Extended operation temperature: -40 °C to +85 °C* Storage temperature -45 °C to +90 °C

### NOTE

Module is able to make and receive voice calls, data calls, SMS and make GPRS/UMTS/HSPA+/LTE traffic in -40 °C ~ +85 °C. The performance will be reduced slightly from the 3GPP specifications if the temperature is outside the normal operating temperature range and still within the extreme operating temperature range.

## 2 Package Information

### 2.1 Pin Assignment Overview

All functions of the module will be provided through 172 pads that will be connected to the customers' platform. The following Figure is a high-level view of the pin assignment of the module.

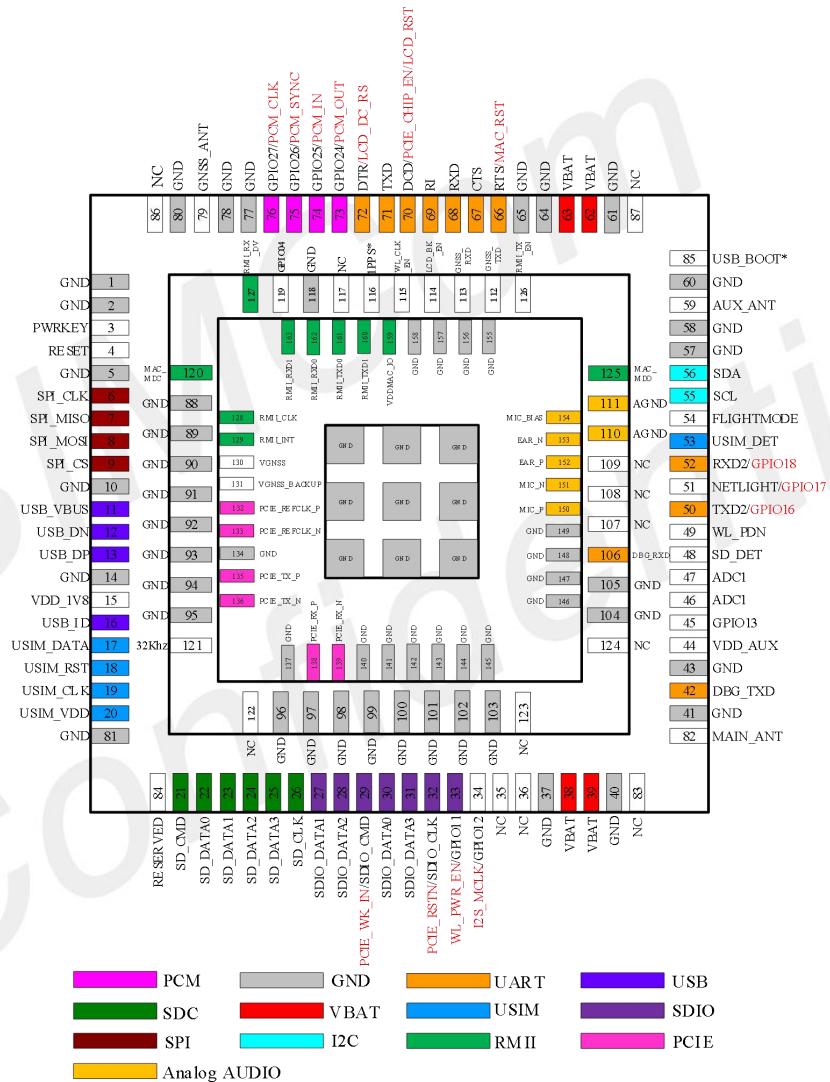


Figure 2: Pin Assignment Overview

#### NOTE

The pins that have 2 or 3 names means the pin have different function, the black color is the default function, and the red color is the multiplex function.

Table 3: Pin Definition

Pin No.	Pin name	Pin No.	Pin name
1	GND	2	GND
3	PWRKEY	4	RESET
5	GND	6	SPI_CLK
7	SPI_MISO	8	SPI_MOSI
9	SPI_CS	10	GND
11	USB_VBUS	12	USB_DN
13	USB_DP	14	GND
15	VDD_1V8	16	USB_ID
17	USIM_DATA	18	USIM_RST
19	USIM_CLK	20	USIM_VDD
21	SD_CMD	22	SD_DATA0
23	SD_DATA1	24	SD_DATA2
25	SD_DATA3	26	SD_CLK
27	SDIO_DATA1	28	SDIO_DATA2
29	PCIE_WK_IN/SDIO_CMD	30	SDIO_DATA0
31	SDIO_DATA3	32	PCIE_RSTN/SDIO_CLK
33	WL_PWR_EN/GPIO11	34	I2S_MCLK/GPIO12
35	NC	36	NC
37	GND	38	VBAT
39	VBAT	40	GND
41	GND	42	DBG_TXD
43	GND	44	VDD_AUX
45	GPIO13	46	ADC1
47	ADC1	48	SD_DET
49	WL_PDN	50	TXD2/GPIO16
51	NETLIGHT/GPIO17	52	RXD2/GPIO18
53	USIM_DET	54	FLIGHTMODE
55	SCL	56	SDA
57	GND	58	GND
59	AUX_ANT	60	GND
61	GND	62	VBAT
63	VBAT	64	GND
65	GND	66	RTS/MAC_RST
67	CTS	68	RXD
69	RI	70	DCD/PCIE_CHIP_EN/LCD_RST
71	TXD	72	DTR/LCD_DC_RS
73	GPIO24/PCM_OUT	74	GPIO25/PCM_IN

75	GPIO26/PCM_SYNC	76	GPIO27/PCM_CLK
77	GND	78	GND
79	GNSS_ANT	80	GND
81	GND	82	MAIN_ANT
83	NC	84	Reserved
85	USB_BOOT*	86	NC
87	NC	88	GND
89	GND	90	GND
91	GND	92	GND
93	GND	94	GND
95	GND	96	GND
97	GND	98	GND
99	GND	100	GND
101	GND	102	GND
103	GND	104	GND
105	GND	106	DBG_RXD
107	NC	108	NC
109	NC	110	AGND
111	AGND	112	GNSS_TXD
113	GNSS_RXD	114	LCD_BK_EN
115	WL_CLK_EN	116	1PPS*
117	NC	118	GND
119	GPIO04	120	MAC_MDC
121	32KHZ*	122	NC
123	NC	124	NC
125	MAC_MDO	126	RMII_TX_EN
127	RMII_RX_DV	128	RMII_CLK
129	RMII_INT	130	VGNSS
131	VGNSS_BACKUP	132	PCIE_REFCLK_P
133	PCIE_REFCLK_N	134	GND
135	PCIE_TX_P	136	PCIE_TX_N
137	GND	138	PCIE_RX_P
139	PCIE_RX_N	140	GND
141	GND	142	GND
143	GND	144	GND
145	GND	146	GND
147	GND	148	GND
149	GND	150	MIC_P
151	MIC_N	152	EAR_P
153	EAR_N	154	MIC_BIAS
155	GND	156	GND

<b>157</b>	GND	<b>158</b>	GND
<b>159</b>	VDDMAC_IO	<b>160</b>	RMII_TXD1
<b>161</b>	RMII_RXD0	<b>162</b>	RMII_RXD0
<b>163</b>	RMII_RXD1	<b>164</b>	GND
<b>165</b>	GND	<b>166</b>	GND
<b>167</b>	GND	<b>168</b>	GND
<b>169</b>	GND	<b>170</b>	GND
<b>171</b>	GND	<b>172</b>	GND

**NOTE**

Before the normal power on, the USB\_BOOT cannot be pull down to ground, otherwise module will not be powered up normally.

## 2.2 Pin Description

Table 4: IO Parameters Definition

Pin Type	Description
PI	Power input
PO	Power output
AI	Analog input
AIO	Analog input/output
I/O	Bidirectional input /output
DI	Digital input
DO	Digital output
DIO	Digital input/output
DOH	Digital output with high level
DOL	Digital output with low level
PU	Pull up
PD	Pull down

Table 5: Electric Feature

Power domain	Symbol	Description	Min	Typ	Max
P3	1.8 V				
	VOH	Output high	1.6 V	-	1.8 V
	VOL	Output low	0 V	-	0.2 V
	VIH	Input high	1.26 V	1.8 V	2.0 V
	VIL	Input low	-0.3 V	0 V	0.54 V
	Rpu	Pull-up resiter	55 KΩ	79 KΩ	121 KΩ
	Rpd	Pull-down resiter	51 KΩ	87 KΩ	169 KΩ
P5,P8	1.8 V				
	VOH	Output high	1.6 V	-	1.8 V
	VOL	Output low	0 V	-	0.2 V
	VIH	Input high	1.26 V	1.8 V	2.0 V
	VIL	Input low	-0.3 V	-	0.54 V
	Rpu	Pull-up resiter	55 KΩ	79 KΩ	121 KΩ
	Rpd	Pull-down resiter	51 KΩ	87 KΩ	169 KΩ
P6	3.0 V				
	VOH	Output high	2.4 V	-	-
	VOL	Output low	0 V	-	0.4 V
	VIH	Input high	2 V	-	3.3 V
	VIL	Input low	-0.3 V	0 V	0.8 V
	Rpu	Pull-up resiter	26 KΩ	47 KΩ	72 KΩ
	Rpd	Pull-down resiter	27 KΩ	54 KΩ	267 KΩ
P6	1.8 V				

VOH	Output high	1.6 V	-	1.8 V
VOL	Output low	0 V	-	0.2 V
VIH	Input high	1.26 V	1.8 V	2.0 V
VIL	Input low	-0.3 V	-	0.54 V
Rpu	Pull-up resiter	55 KΩ	79 KΩ	121 KΩ
Rpd	Pull-down resiter	51 KΩ	87 KΩ	169 KΩ
3.3 V				
VOH	Output high	2.4 V	-	-
VOL	Output low	0 V	-	0.4 V
VIH	Input high	2 V	-	3.6 V
VIL	Input low	-0.3 V	0 V	0.8 V
Rpu	Pull-up resiter	26 KΩ	47 KΩ	72 KΩ
Rpd	Pull-down resiter	27 KΩ	54 KΩ	267 KΩ

Table 6: Pin Description

Pin Name	Pin No.	Power Domain	Defalt Stats	Description	Comment
<b>Power supply</b>					
VBAT	38,39,62,63	-	PI	Power supply for the module.	Power supply, voltage range: 3.4 ~ 4.2 V.
VDD_AUX	44	-	PO	LDO power output for other external circuits with Max 150 mA current output. Its output voltage is 2.85 V fixed.	If unused, keep it open.
VDD_1V8	15	-	PO	1.8 V output with Max 50 mA current output for external circuit, such as level shift circuit.	If unused, keep it open.
GND	1,2,5,10,14,3 7,40,41,43,57 ,58,60,61,64, 65,77,78,80,8 1,88~105,118 ,134,137,140 ~149,155~15 8,164~172	-	-	Ground	
RESERVED	84				Keep these pins unconnected
NC	35,36,83,86,8 7,107~109,11 7,122~124				Keep these pins unconnected
PWRKEY	3	-	DI,PU	System power on/off control input, active low.	It has been pulled up to VBAT via 50 KΩ resistor internally.
RESET	4	-	DI, PU	System reset control input, active low.	It has been pulled up to VBAT via 50 KΩ resistor internally.

### SD Interface

SD_CMD	21	P8	I/O, PU	SD Card Bidirectional command/response signal.	
SD_DATA0	22	P8	I/O, PU	SD Card Bidirectional data signal bit 0.	The power domain of SD I/O pins depends on P8. If unused, keep them open.
SD_DATA1	23	P8	I/O, PU	SD Card Bidirectional data signal bit 1.	
SD_DATA2	24	P8	I/O, PU	SD Card Bidirectional data signal bit 2.	
SD_DATA3	25	P8	I/O, PU	SD Card Bidirectional data signal bit 3.	
SD_CLK	26	P8	I/O, PD	SD Card clock.	
SD_DET	48	P3	DI, PU	SD hot-plug detect.	Default: GPIO Optional: SD card detecting input. H: SD card is removed L: SD card is inserted. Pull it up to VDD_EXT with a 100 kΩ resistor. If unused, keep it open.

### USIM Interface

USIM_DATA	17	P5	I/O, PU	USIM Card data.	which has been pulled up via 4.7 KΩ resistor to USIM_VDD internally. Do not pull it up or down externally.
USIM_RST	18	P5	DO, PU	USIM Card reset.	
USIM_CLK	19	P5	DO, PU	USIM Card clock.	
USIM_VDD	20	-	PO	USIM Card power supply.	its output Voltage depends on USIM card type automatically. Its output current is up to 50 mA.
USIM_DET	53	P3	DI,PU	USIM Card hot-plug detect.	Default: GPIO Optional: USIM card detecting input. H: USIM is removed L: USIM is inserted

### USB Interface

USB_VBUS	11	-	AI	Valid USB detection input with 3.6~5.25 V detection voltage.	For USB connection detection only, not power supply.
USB_DN	12	-	AIO	Negative line of the differential, bi-directional	Requires differential

				USB signal.	impedance of 90 Ω. USB 2.0 supports downward compatibility.
USB_DP	13	-	AIO	Positive line of the differential, bi-directional USB signal.	
USB_ID	16	-	DI, PU	USB ID input	Keep it open.
<b>MAIN UART</b>					
TXD	71	P3	DO, PU	Transmit data.	
RXD	68	P3	DI,PU	Receive data	
RTS	66	P3	DO,PU	DTE request to send.	
CTS	67	P3	DI,PU	DCE clear to send.	
RI	69	P3	DO,PU	Ring Indicator	
DCD	70	P3	DO, PU	Data carrier detect.	
DTR	72	P3	DI, PU	Data terminal ready, sleep mode control.	
<b>GNSS UART</b>					
TXD2	50	P3	DO,PU	Transmit data for GNSS communication.	
RXD2	52	P3	DI, PU	Receive data for GNSS communication.	
<b>Debug UART</b>					
DBG_TXD	42	P3	DO, PU	Transmit data for debug.	
DBG_RXD	106	P3	DI, PU	Receive data for debug.	Print Kernel log
<b>PCM Interface</b>					
PCM_OUT	73	P3	DO, PD	PCM data output.	
PCM_IN	74	P3	DI, PD	PCM data input.	
PCM_SYNC	75	P3	DO,PD	PCM data frame sync signal.	
PCM_CLK	76	P3	DO, PD	PCM data bit clock.	
I2S_MCLK	34	P3	DO, PD	Provides digital clock output for external audio codec.	
<b>SPI Interface</b>					
SPI_CLK	6	P3	DO, PD	SPI clock output	
SPI_MISO	7	P3	DI, PD	SPI master in/slave out data	
SPI_MOSI	8	P3	DO, PD	SPI master out/slave in data	
SPI_CS	9	P3	DO, PD	SPI chip-select output	
<b>LCD Control Interface</b>					
LCD_DC_RS	72	P3	DO,PU	LCD data/command select	
LCD_RST	70	P3	DO,PU	LCD reset	
LCD_BK_EN	114	P3	DO,PD	LCD Backlight control	
<b>I2C interface</b>					
SCL	55	P3	OD,PU	I2C serial clock output	It has been pulled up to VDD_1V8 via 2.2 KΩ

SDA	56	P3	OD,PU	I2C serial data input/output	resistor internally. If unused, keep them open.
<b>SDIO Interface</b>					
SDIO_DATA0	30	P3	I/O, PU	Secure digital controller data bit 0	
SDIO_DATA1	27	P3	I/O, PU	Secure digital controller data bit 1	
SDIO_DATA2	28	P3	I/O, PU	Secure digital controller data bit 2	
SDIO_DATA3	31	P3	I/O, PU	Secure digital controller data bit 3	
SDIO_CLK	32	P3	DO, PU	Secure digital controller clock	
SDIO_CMD	29	P3	I/O, PU	Secure digital Controller command/response signal	
<b>WIFI Control Interface</b>					
WL_PDN	49	P3	DO, PU	WIFI chip enable.	Active high.If unused, please keep them open.
WL_PWR_EN	33	P3	DO, PD	WIFI power enable.	
WL_CLK_EN	115	P3	DO, PD	WIFI Clock enable.	If unused, please keep it open.
<b>PCIe Interface*</b>					
PCIE_WK_IN	29	P3	DI,PU	PCIe wake up host	
PCIE_RST	32	P3	DO,PU	PCIe reset signal	
PCIE_CHIP_EN	70	P3	DO,PU	Chip enable	
PCIE_REFCLK_P	132	-	AO	PCIe reference clock positive	Only support host mode, it can connect WiFi chip or other chip.
PCIE_REFCLK_N	133	-	AO	PCIe reference clock negative	
PCIE_TX_P	135	-	AO	PCIe transmit positive	
PCIE_TX_N	136	-	AO	PCIe transmit negative	
PCIE_RX_P	138	-	AI	PCIe receive positive	
PCIE_RX_N	139	-	AI	PCIe receive negative	
<b>Analog Audio Interface</b>					
AGND	110,111	-	PI	Analog Ground	
MIC_P	150	-	AI	Microphone input positive	
MIC_N	151	-	AI	Microphone input negative	
EAR_P	152	-	AO	Earphone output positive	
EAR_N	153	-	AO	Earphone output negative	
MIC_BIAS	154	-	PO	Microphone bias voltage	
<b>RMII Interface</b>					
RMII_CLK	128	P6	DI,PU	RMII Clock	
RMII_INT	129	P6	DI, PU	PHY interrupt output	
RMII_TXD0	161	P6	DO,PU	RMII transmit data bit 0	
RMII_TXD1	160	P6	DO,PU	RMII transmit data bit 1	

RMII_RXD0	162	P6	DI, PU	RMII receive data bit 0	
RMII_RXD1	163	P6	DI, PU	RMII receive data bit 1	
RMII_RX_DV	127	P6	DI, PU	RMII receive control	
RMII_TX_EN	126	P6	DO,PD	RMII transmit control	
VDDMAC_IO	159	P6	PI	MAC IO voltage configure	
<b>MAC Control Interface</b>					
MAC_MDC	120	P6	DO,PD	MAC management Clock	
MAC_MDIO	125	P6	OD,PU	MAC management data	Need pull it up to PHY VIO with an external 1.5 KΩ resistor;
<b>GNSS Control Interface</b>					
VGNSS	130	-	PI	GNSS supply voltage	Power supply, voltage range: 1.7 ~ 1.9 V.
VGNSS_BACK_UP	131	-	PI	GNSS backup battery	Power supply, voltage range: 1.4 ~ 3.6 V.
GNSS_TXD	112	-	DO	GNSS NMEA data port	
GNSS_RXD	113	-	DI	GNSS NMEA data port	
1PPS*	116	-	-	-	In developing
<b>GPIO Interface</b>					
GPIO11	33	P3	DIO,PD	General input/output 11	
GPIO12	34	P3	DIO,PD	General input/output 12	
GPIO13	45	P3	DIO,PU	General input/output 13	
GPIO24	73	P3	DIO,PD	General input/output 24	
GPIO25	74	P3	DIO,PD	General input/output 25	
GPIO26	75	P3	DIO,PD	General input/output 26	
GPIO27	76	P3	DIO,PD	General input/output 27	
<b>RF Interface</b>					
MAIN_ANT	82		AI0	MAIN antenna soldering pad	
GNSS_ANT	79		AI	GNSS antenna soldering pad	
AUX_ANT	59		AI	Auxiliary soldering pad	antenna
<b>Other Interface</b>					
ADC1	46,47	-	AI	Analog-digital converter input 1	Max input voltage 1.8V
NETLIGHT	51	P3	DO,PD	LED control output as network status indication.	
FLIGHTMODE	54	P3	DI,PD	Flight Mode control input. High level(or open): Normal Mode Low level: Flight Mode	
USB_BOOT*	85	P3	DI,PD	Forces the module to enter emergency download mode	

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32KHZ\*

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DO,PD

In developing

SIMCom  
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## 2.3 Mechanical Information

The following figure shows the package outline drawing of module.

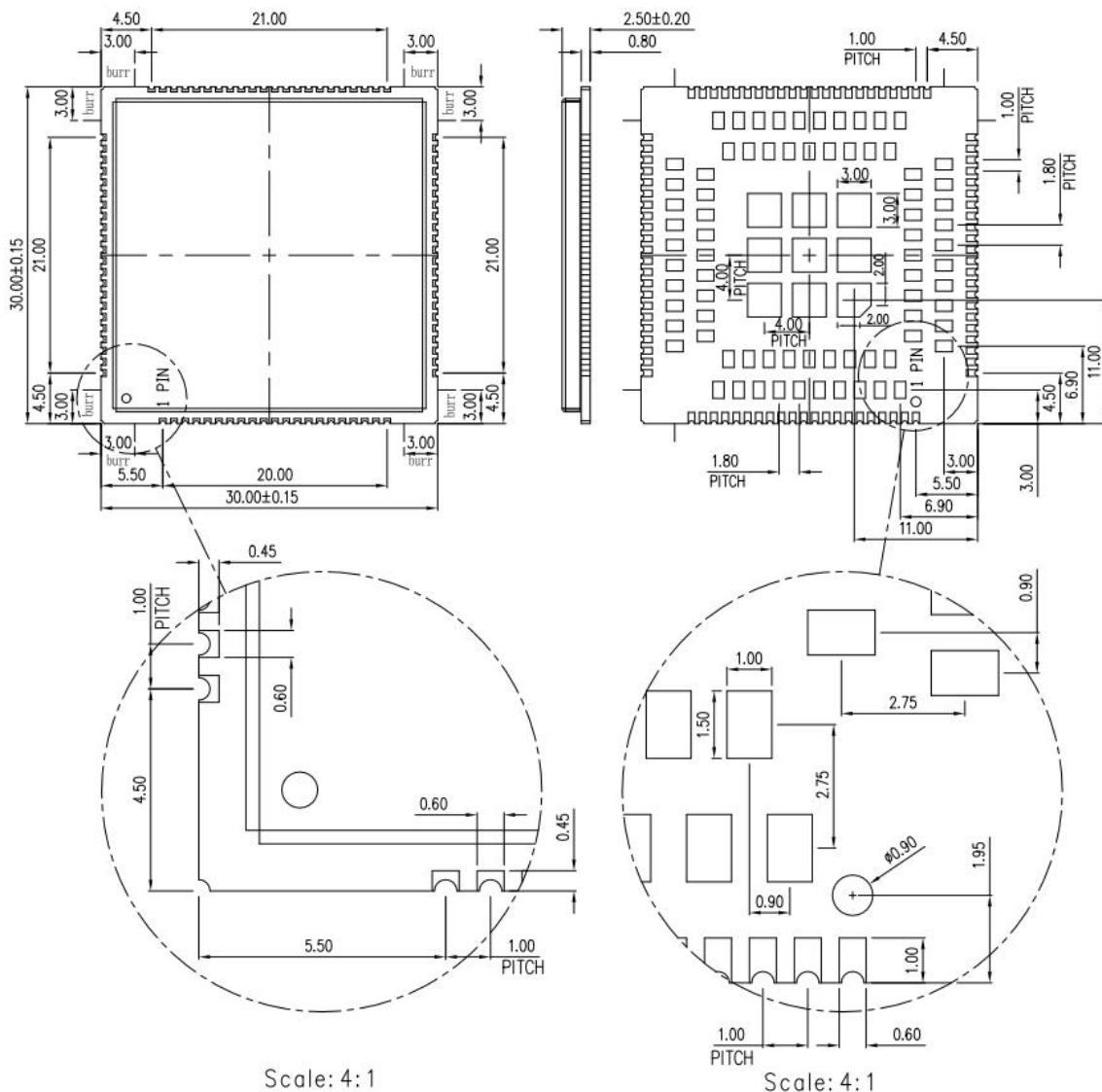


Figure 3: Mechanical Dimensions (Unit: mm)

## 2.4 Footprint Recommendation

Recommended PCB  
footprint ourline  
(Unit:mm)

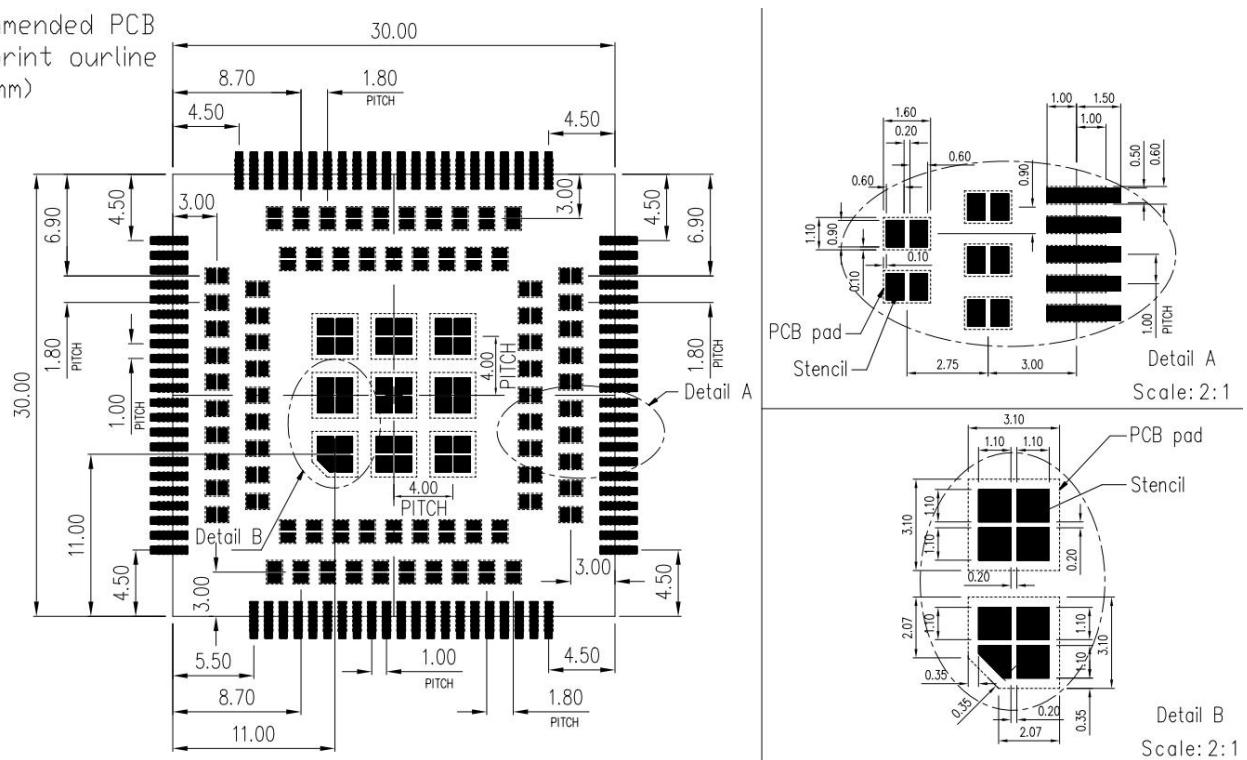


Figure 4: Footprint Recommendation (Unit: mm)

## 3 Interface Application

### 3.1 Power Supply

The power supply pins of module include 4 pins (pin 62&63, pin 38&39) named VBAT.

The 4 VBAT pads supply the power to RF and baseband circuits directly.

On VBAT pads, the ripple current up to 2 A typically, due to GSM/GPRS emission burst (every 4.615 ms), may cause voltage drop. So the power supply for these pads must be able to provide sufficient current up to more than 2 A in order to avoid the voltage drop is more than 300 mV.

The following figure shows the VBAT voltage ripple wave at the maximum power transmit phase.

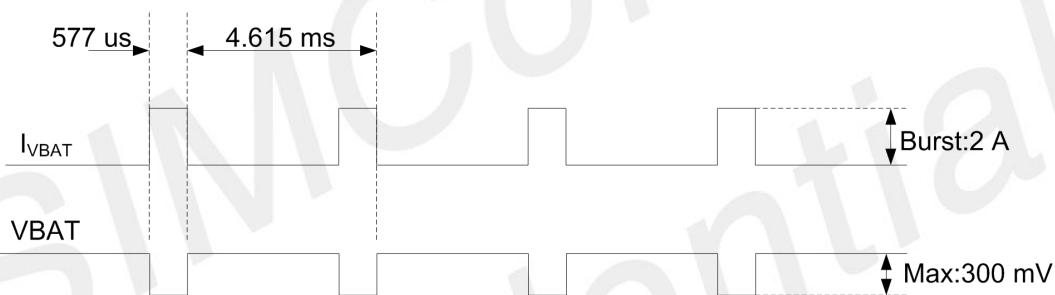


Figure 5: VBAT Voltage Drop during Burst Emission (GSM/GPRS)

#### NOTE

The test condition: The voltage of power supply for VBAT is 3.8 V, Cd=100  $\mu$ F tantalum capacitor (ESR=0.7  $\Omega$ ) and Cf=100 nF (Please refer to Figure 6 application circuit).

Table 7: VBAT Electronic Characteristic

Symbol	Description	Min.	Typ.	Max.	Unit
VBAT	Module power voltage	3.4	3.8	4.2	V
I <sub>VBAT(peak)</sub>	Module power peak current in normal mode.	-	2	-	A
I <sub>VBAT(average)</sub>	Module power average current in normal mode	Please refer to the table 34			
I <sub>VBAT (sleep)</sub>	Power supply current in sleep mode				
I <sub>VBAT (power-off)</sub>	Module power current in power off mode.	150			uA

### 3.1.1 Power Supply Design Guide

Make sure that the voltage on the VBAT pins will never drop below 3.4 V, even during a transmit burst, when current consumption may rise up to 2 A. If the voltage drops below 3.4 V, the RF performance may be affected.

#### NOTE

If the power supply for VBAT pins can support up to 2 A, more than 300 uF capacitors are recommended. Otherwise users must use a total of 1000 uF capacitors typically, in order to avoid of the voltage drop more than 300 mV.

Some multi-layer ceramic chip (MLCC) capacitors (0.1/1 uF) with low ESR in high frequency band can be used for EMC.

These capacitors should be put as close as possible to VBAT pads. Also, users should keep VBAT trace on circuit board wider than 2 mm to minimize PCB trace impedance. The following figure shows the recommended circuit. Recommend part of FB101 is BLM21PG300SN1D or MPZ2012S221A.

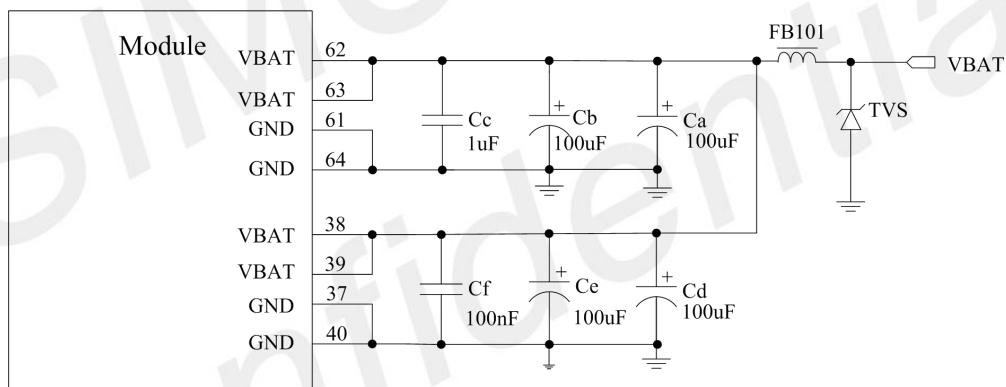


Figure 6: Power Supply Application Circuit

In addition, in order to guard for ESD or surge protection, it is suggested to use a TVS to protect the module.

#### NOTE

Customer could only power pin 62, 63 or only power pin 38, 39, for these pins are connected inside the module.

**Table 8: Recommended TVS List**

No	Manufacturer	Part Number	Reverse Stand-Off Voltage	Package
1	Js-ele	ESDBW5V0A1	5 V	DFN1006-2L
2	Prisem	PESDHC2FD4V5BH	4.5 V	DFN1006-2L
3	Way-on	WS05DPF-B	5 V	DFN1006-2L
4	Will semi	ESD5611N	5 V	DFN1006-2L
5	Will semi	ESD56151W05	5 V	SOD-323
6	Way-on	WS4.5DPV	4.5 V	DFN1610-2L

### 3.1.2 Recommended Power Supply Circuit

It is recommended that a switching mode power supply or a linear regulator power supply is used. It is important to make sure that all the components used in the power supply circuit can resist a peak current up to 2 A.

The following figure shows the linear regulator reference circuit with 5 V input and 3.8 V output.

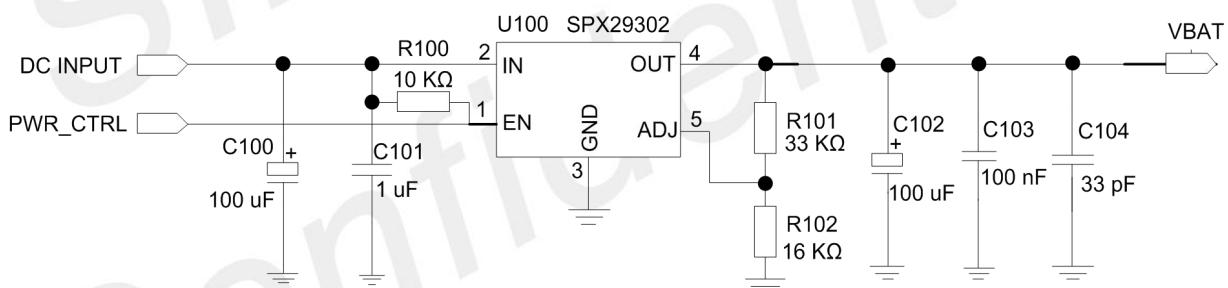


Figure 7: Linear Regulator Reference Circuit

If there is a big voltage difference between input and output for VBAT power supply, or the efficiency is extremely important, then a switching mode power supply will be preferable. The following figure shows the switching mode power supply reference circuit.

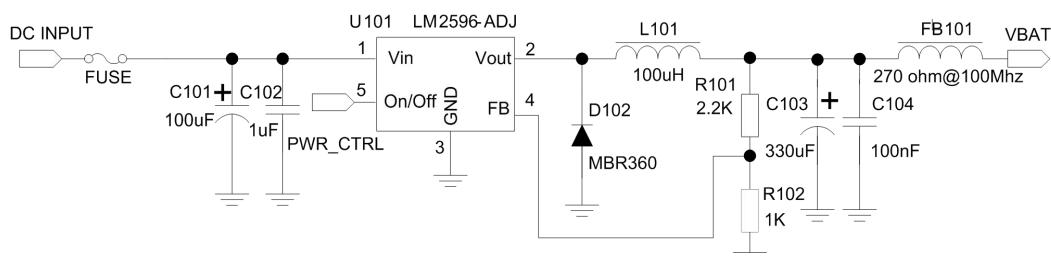


Figure 8: Switching Mode Power Supply Reference Circuit

### NOTE

1. The Switching Mode power supply solution for VBAT must be chosen carefully against Electro Magnetic Interference and ripple current from degrading RF performance.
2. If the DC input is 12 V, customer must select a buck circuit to get better power efficiency.

### 3.1.3 Voltage Monitor\*

To monitor the VBAT voltage, the AT command “AT+CBC” can be used.

For monitoring the VBAT voltage outside or within a special range, the AT command “AT+CVALARM” can be used to enable the under-voltage warning function.

If users need to power off module, when the VBAT voltage is out of a range, the AT command “AT+CPMVT” can be used to enable under-voltage power-off function.

### NOTE

1. Under-voltage warning function and under-voltage power-off function are disabled by default. For more information about these AT commands, please refer to Document [1].
2. “\*” means under development.

## 3.2 Power on/Power off/Reset Function

### 3.2.1 Power on

Module can be powered on by pulling the PWRKEY pin down to ground.

The PWRKEY pin has been pulled up with a diode to VBAT internally, so it does not need to be pulled up externally. It is strongly recommended to put an ESD protection diode, close to the PWRKEY pin as it would strongly enhance the ESD performance of PWRKEY pin. Please refer to the following figure for the recommended reference circuit.

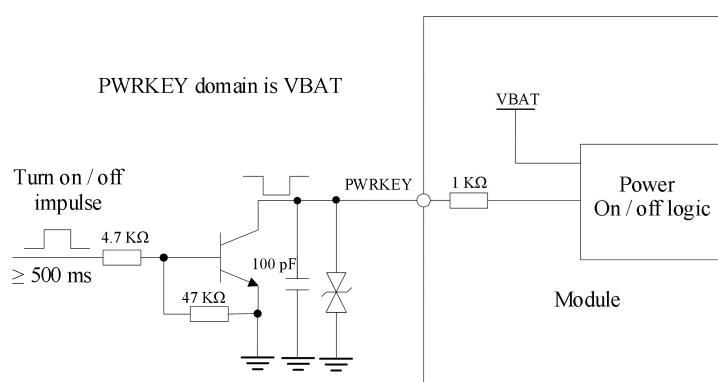


Figure 9: Reference Power On/off Circuit

**NOTE**

Module could be automatically power on by connecting PWRKEY pin to ground via  $0\ \Omega$  resistor directly.

The power-on scenarios are illustrated in the following figure.

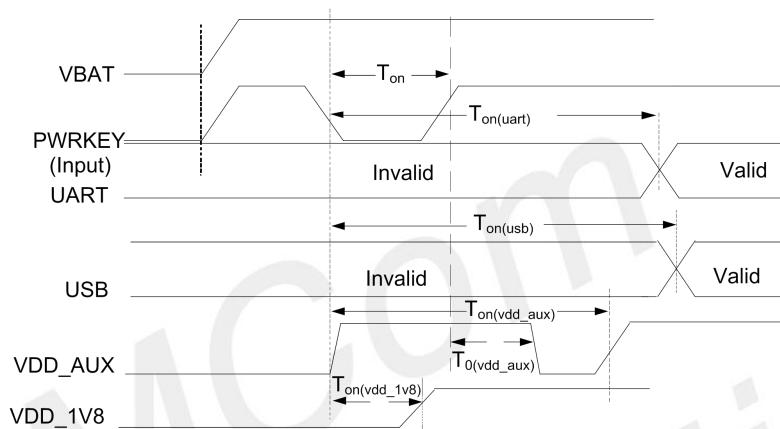


Figure 10: Power On Timing Sequence

Table 9: Power On Timing and Electronic Characteristic

Symbol	Parameter	Min.	Typ.	Max.	Unit
$T_{on}$	The time of active low level impulse of PWRKEY pin to power on module	500	1000	2000	ms
$T_{on(uart)}$	The time from power-on issue to UART port ready	15	-	-	s
$T_{on(vdd\_aux)}$	The time from power-on issue to VDD_AUX ready	20	-	-	s
$T_0(vdd\_aux)$	The VDD_AUX is on before the software ready	3	-	-	s
$T_{on(vdd\_1v8)}$	The time from power-on issue to VDD_1V8 ready	100	-	-	ms
$T_{on(usb)}$	The time from power-on issue to USB port ready	20	25	-	s
$V_{IH}$	Input high level voltage on PWRKEY pin	$0.7*V_{BAT}$	$V_{BAT} + 0.3$		V
$V_{IL}$	Input low level voltage on PWRKEY pin	-0.3	0	0.5	V

**NOTE**

The time may vary for the different software version;

When the  $T_{on}$  time less than 500ms, the module might power on, but only the  $T_{on}$  time more than 500 ms, the module will power on is guaranteed.

### 3.2.2 Power off

The following methods can be used to power off module.

- Method 1: Power off module by pulling the PWRKEY pin down to ground.
- Method 2: Power off module by AT command “AT+CPOF”. \*
- Method 3: Over-voltage or under-voltage automatic power off. The voltage range can be set by AT command “AT+CPMVT”. \*
- Method 4: Over-temperature or under-temperature automatic power off.

#### NOTE

If the temperature is outside the range of -30~+80 °C, some warning will be reported via AT port. If the temperature is outside the range of -40~+85 °C, module will be powered off automatically.

“AT+CPOF” and “AT+CPMVT” in developing;

These procedures will make module disconnect from the network and allow the software to enter a safe state, and save data before module be powered off completely.

The power off scenario by pulling down the PWRKEY pin is illustrated in the following figure.

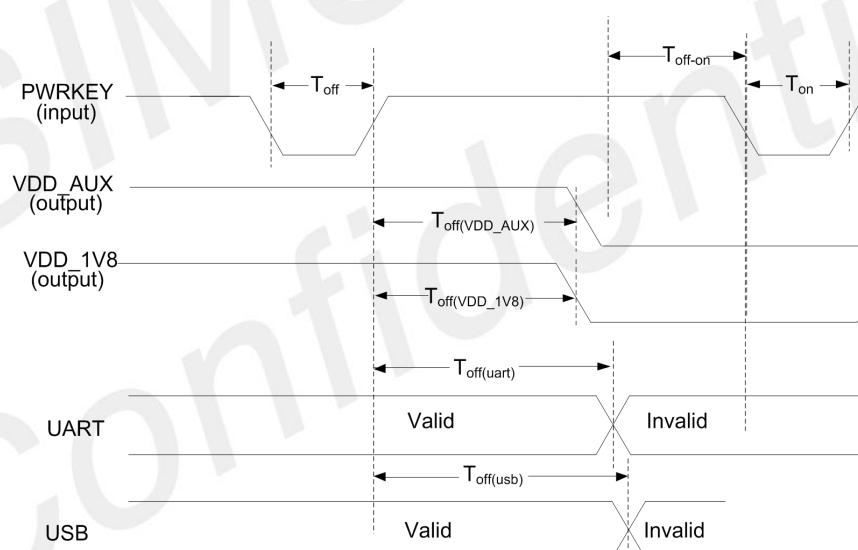


Figure 11: Power Off Timing Sequence

Table 10: Power Off Timing and Electronic Characteristic

Symbol	Parameter	Min.	Typ.	Max.	Unit
$T_{off}$	The active low level time pulse on PWRKEY pin to power off module	2.5	--	5.0	s
$T_{off(uart)}$	The time from power-off issue to UART port off	TBD	TBD	-	s
$T_{off(usb)}$	The time from power-off issue to USB port off	TBD	TBD	-	s
$T_{off(VDD\_AUX)}$	The time from power-off issue to vdd_aux off	TBD	-	-	s

T <sub>off(VDD_1V8)</sub>	The time from power-off issue to vdd_1V8f	TBD	-	-	s
T <sub>off-on</sub>	The buffer time from power-off issue to power-on issue	3	-	-	s

**NOTE**

1. It is suggested that the host can cut off the power off the module, when the module could not switch off by PWRKEY of RESET interface, customer could cut off the power to restart the module.
2. If the PWERKY and RESET key works normally, it is not suggested to switch off module by remove the power supply for that might damage the flash.
3. The power off time may vary for the local net status.

### 3.2.3 Reset Function

Module can be reset by pulling the RESET pin down to ground.

#### NOTE

This function is only used as an emergency reset, when AT command “AT+CPOF” and the PWRKEY pin all have lost efficacy.

The RESET pin has been pulled up with a  $40\text{ k}\Omega$  resistor to VBAT internally, so it does not need to be pulled up externally. It is strongly recommended to put a  $100\text{ pF}$  capacitor and an ESD protection diode close to the RESET pin. Please refer to the following figure for the recommended reference circuit.

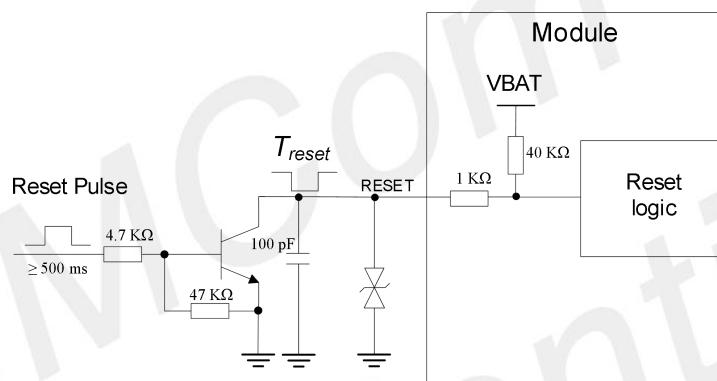


Figure 12: Reference Reset Circuit

Table 11: RESET Electronic Characteristic

Symbol	Parameter	Min.	Typ.	Max.	Unit
$T_{reset}$	The active low level time impulse on RESET pin to reset module	500	1000	2000	ms
$V_{IH}$	Input high level voltage	$0.7 \times V_{BAT}$	$V_{BAT}$	$V_{BAT} + 0.3$	V
$V_{IL}$	Input low level voltage	-0.3	0	0.5	V

#### NOTE

- When the module could not switch off by PWRKEY or RESET interface, customer should cut off the power to restart the module.
- If the PWERKY and RESET key works normally, it is not suggested to switch off module by remove the power supply for that might damage the flash.

### 3.3 UART Interfaces

The module provides three UART interfaces: one MAIN UART interface, one Debug UART interface, and one GNSS UART interface.

- **MAIN UART:** Module provides a 7-wire UART (universal asynchronous serial transmission) interface as DCE (Data Communication Equipment). AT commands and data transmission can be performed through UART interface.
- **Debug UART:** Used for Linux console and log output.  
Default baud rate: 115200 bps
- **GNSS UART:** Used for GNSS communication.  
Default baud rate: 9600bps

#### 3.3.1 MAIN UART Design Guide

The following figures show the reference design.

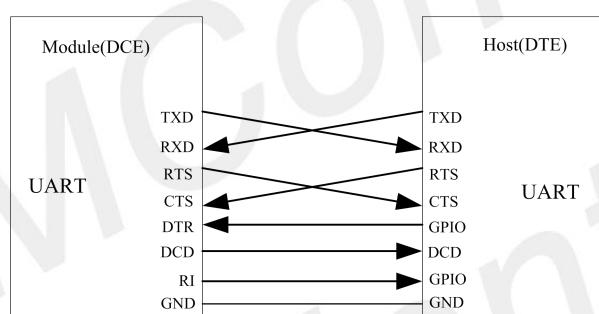


Figure 13: UART Full Modem

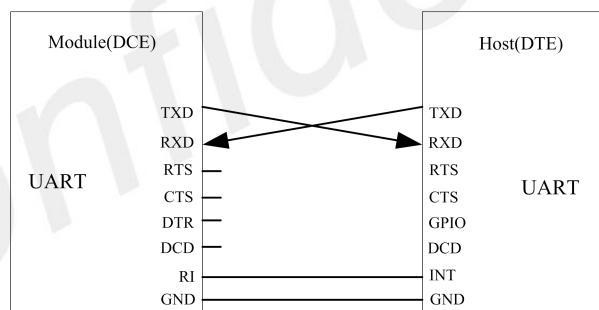


Figure 14: UART Null Modem

The module UART is 1.8 V voltage interface. If user's UART application circuit is 3.3 V voltage interface, the level shifter circuits should be used for voltage matching. The TXB0108RGYR provided by Texas Instruments is recommended. The following figure shows the voltage matching reference design.

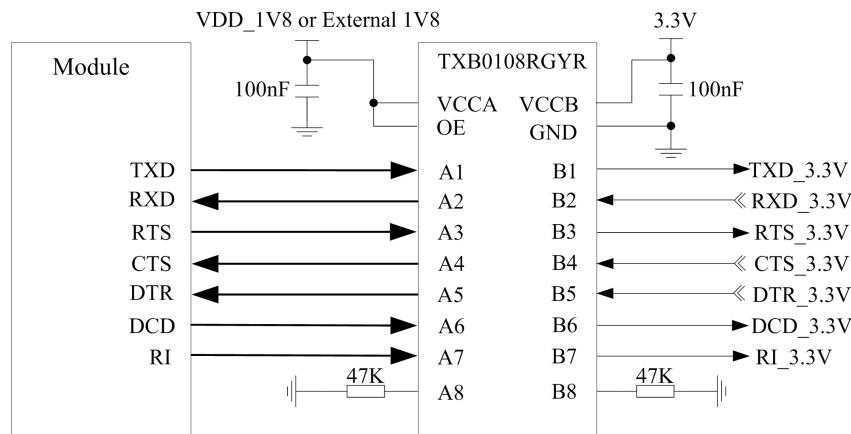


Figure 15: Reference Circuit of Level Shift

Customers can use another level shifter circuits as follow.

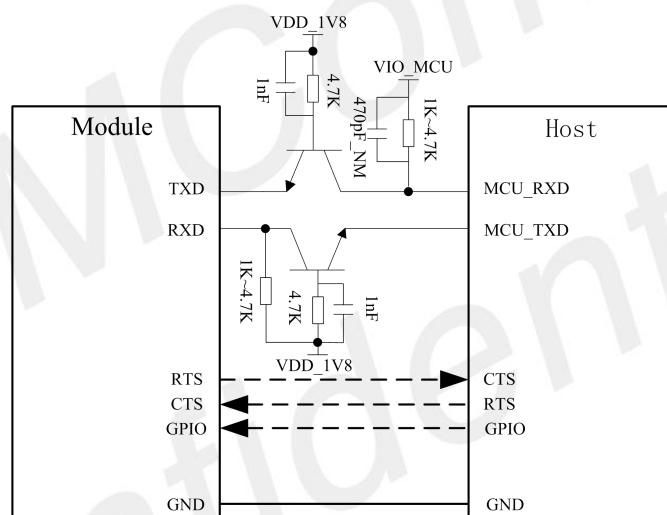


Figure 16: Level Matching Circuit With Triode

**NOTE**

1. User need to use high speed transistors such as MMBT3904.
2. MAIN UART supports the following baud rates: 9600, 19200, 38400, 57600, 115200, 230400, 460800, 921600, 1843200, 3686400 bps. The default band rate is 115200 bps.

### 3.3.2 RI and DTR Behavior

The RI pin can be used to interrupt output signal to inform the host controller such as application CPU.

Normally RI will keep high level until certain conditions such as receiving SMS, or a URC report coming, and then it will change to low level.

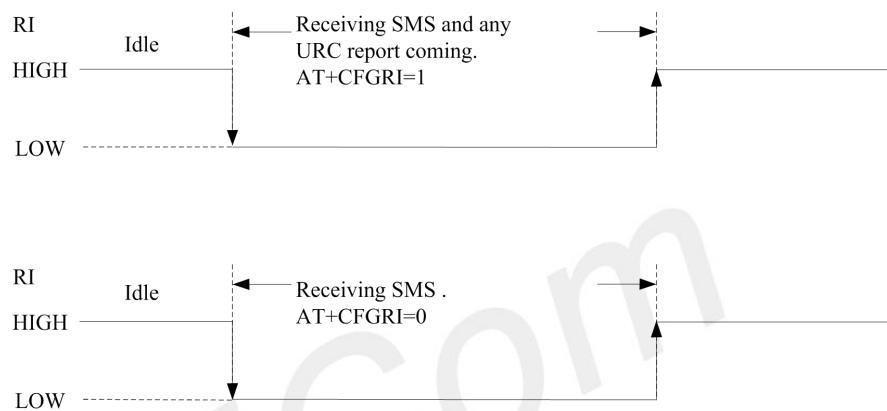


Figure 17: RI Behaviour (SMS and URC report)

Normally RI will be kept at a high level until a voice call, then it will output periodic rectangular wave with 5900 ms low level and 100ms high level. It will output this kind of periodic rectangular wave until the call is answered or hung up.

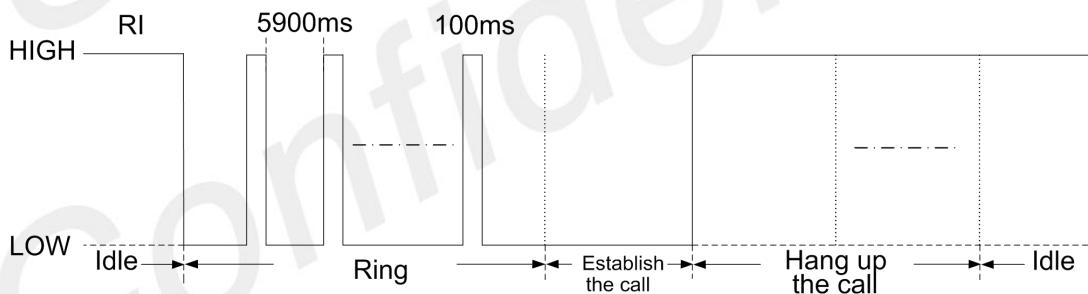


Figure 18: RI Behaviour (Voice Call)

#### NOTE

For more details of AT commands about UART, please refer to document [1] and [22].

DTR pin can be used to wake module from sleep. When module enters sleep mode, pulling down DTR can wake module.

## 3.4 USB Interface

The module contains a USB interface compliant with the USB2.0 specification as a peripheral, but the USB charging function is not supported.

### 3.4.1 USB Diagram

Module can be used as a USB device. module supports the USB suspend and resume mechanism which can reduce power consumption. If there is no data transmission on the USB bus, module will enter suspend mode automatically, and will be resumed by some events such as voice call, receiving SMS, etc. The USB interface is a frequency used debug port; it is suggested to reserved test point.

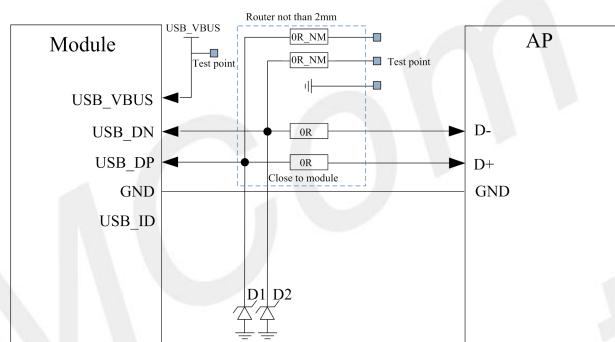


Figure 19: USB Reference Circuit

Because of the high bit rate on USB bus, more attention should be paid to the influence of the junction capacitance of the ESD component on USB data lines. Typically, the capacitance should be less than 1 pF. It is recommended to use an ESD protection component such as ESD9L5.0ST5G provided by On Semiconductor ([www.onsemi.com](http://www.onsemi.com) ).

#### NOTE

The USB\_DN and USB\_DP nets must be traced by 90 Ω+/-10% differential impedance.

### 3.4.2 USB\_BOOT

Module can enter in download mode by USB\_BOOT.

Table 12: USB\_BOOT Description

PIN No	PIN Name	I/O	description	Power domain	Default status	Index
85	USB_BOOT	DI	USB boot	1.8 V	B-PU	

If the module download failed, then customer can make module enter download mode via this Pin. Before the module power on, pull the USB\_BOOT to ground, then push the PWRKEY to power on module, when the module enter download mode, the pull down should be removed.

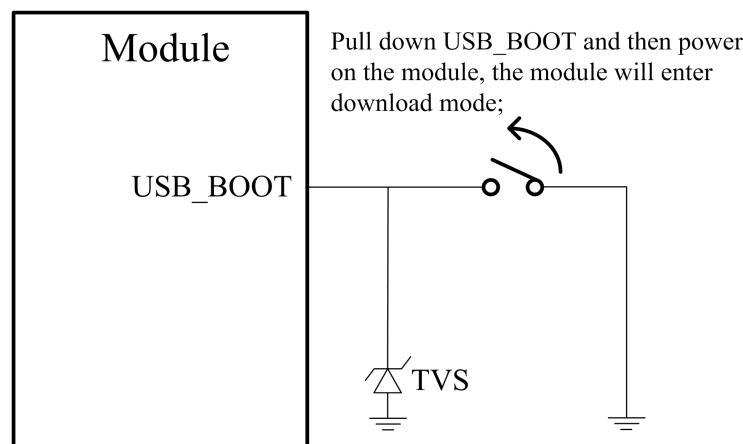


Figure 20: USB\_BOOT Circuit

Customer can check the download port in the device management.



Figure 21: USB Download Port

### 3.4.3 USB\_ID

Module support OTG function, but the USB\_VBUS(PIN 11) cannot supply device with 5 V, so customer should design the circuit to power the USB device.

Table 13: USB\_ID Description

PIN No	PIN Name	I/O	Function description	Domain	Default Status	index
16	USB_ID	DI	High level: module in USB device mode. Low level: module in USB host mode.	1.8 V	DI-PH	

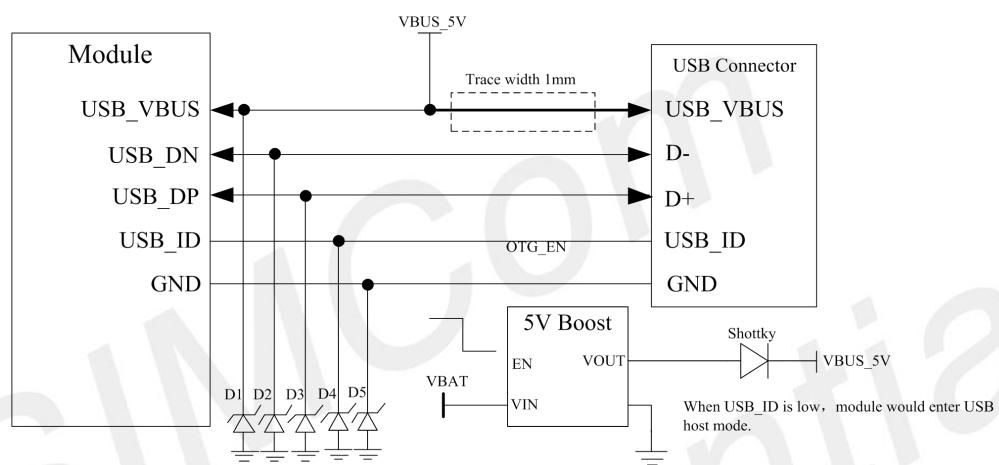


Figure 22: USB\_OTG Diagram

### 3.5 Analog Audio

The module support 1 pair of audio input(MIC\_P,MIC\_N) for microphone, and support 1 pair of audio output for earphone.

Table 14: Audio Interface Definition

PIN No	PIN Name	I/O	Function description	Power domain	Default	Index
150	MIC_P	AI	Mic input positive	-	-	
151	MIC_N	AI	Mic input negative	-	-	
152	EAR_P	AO	Earphone output positive	-	-	
153	EAR_N	AO	Earphone output negative	-	-	
154	MIC_BIAS	PO	Mic bias voltage	-	-	
110,111	AGND	-	Analog ground	-	-	

Customer could use “AT+CMIC” to tune the gain of microphone input signal, “AT+CLVL” could be used to tune the gain of output gain.

The following figure shows the reference circuit.

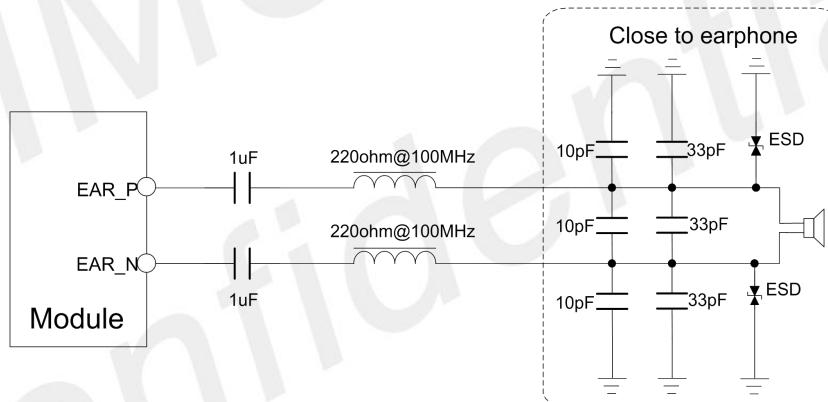


Figure 23: Receiver Circuit

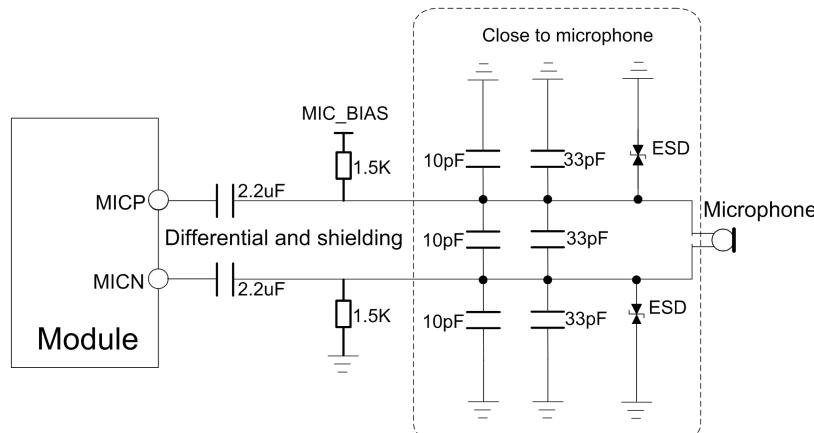


Figure 24: Microphone Circuit

**Table 15: Audio Input Parameter**

Parameter	Test condition	Min	Typ	Max	Unit
Mic bias voltage		-	1.8	-	V
Working current		-	-	2.0	mA
Dynamic Range	Measured as THD+N at 60dB below full scale, 0dB PGA gain,20~20KHz	-	91	-	dB
Peak-SNDR	-4dBFS output, at 0dB gain	-	86	-	
THD	-1dBFS output, at 0dB gain	-	80	-	dB
PGA+ADC gain options	GAIN=(0dB,6dB,12dB,18dB,24dB)	-	12	-	dB

**Table 16: Audio Output Parameter**

Parameter	Test condition	Dynamic Range (Typ)	THD+N(Typ)	Power (1% THD)
Output	RL=32 Ω eraphone	-	15	90
DAC	RL=10K Ω	101 dBA	-96 dB(@vout - 2 dBv)	1.59 Vp
Class-AB	Mono,32 Ω, differential	100 dBA	-90 dB(0.00316%) (@20 mW output)	37 mW

GSM signal can interfere with audio through coupling and conduction. Users can filter out coupling interference by adding 33 pF and 10 pF capacitors to the audio path. The 33 pF capacitor mainly filters out the interference in the GSM900 frequency band, and the 10 pF capacitor mainly filters out the interference in the DCS1800 frequency band. The coupling interference of TDD has a lot to do with the user's PCB design. In some cases, TDD in the 900 frequency band is more serious, and in some cases, the TDD interference in the 1800 frequency band is more serious. Therefore, the user can select the required filter capacitor according to the actual test results, and sometimes it is not necessary to paste the filter capacitor.

The antenna of GSM is the main source of coupling interference for TDD, so users should pay attention to keeping the audio trace away from the RF antenna and VBAT during PCB layout and wiring. It is best to place a set of audio filter capacitors close to the module end and another set close to the interface end. The audio output should be routed in accordance with the differential signal rules.

The conduction interference is mainly caused by the voltage drop of VBAT. If Audio PA is directly powered by VBAT, it is easier to hear a "squeak" sound at the output of SPK. Therefore, it is best to connect the input of Audio PA in parallel when designing the schematic. Some large value capacitors and series magnetic beads.

TDD and GND are also closely related. If GND is not handled well, many high-frequency interference signals will interfere with MIC and Speaker through bypass capacitors and other components. Therefore, it is important for users to ensure good GND performance during the PCB design stage.

### 3.6 USIM Interface

Module supports both 1.8 V and 3.0 V USIM Cards.

**Table 17: USIM Electronic Characteristic in 1.8 V Mode (USIM\_VDD=1.8 V)**

Symbol	Parameter	Min.	Typ.	Max.	Unit
USIM_VDD	LDO power output voltage	1.75	1.8	1.95	V
$V_{IH}$	High-level input voltage	$0.65 * USIM\_VDD$	-	$USIM\_VDD + 0.3$	V
$V_{IL}$	Low-level input voltage	-0.3	0	$0.35 * USIM\_VDD$	V
$V_{OH}$	High-level output voltage	$USIM\_VDD - 0.45$	-	$USIM\_VDD$	V
$V_{OL}$	Low-level output voltage	0	0	0.45	V

**Table 18: USIM Electronic Characteristic 3.0V Mode (USIM\_VDD=2.95V)**

Symbol	Parameter	Min.	Typ.	Max.	Unit
USIM_VDD	LDO power output voltage	2.75	2.95	3.05	V
$V_{IH}$	High-level input voltage	$0.65 * USIM\_VDD$	-	$USIM\_VDD + 0.3$	V
$V_{IL}$	Low-level input voltage	-0.3	0	$0.25 * USIM\_VDD$	V
$V_{OH}$	High-level output voltage	$USIM\_VDD - 0.45$	-	$USIM\_VDD$	V
$V_{OL}$	Low-level output voltage	0	0	0.45	V

#### 3.6.1 USIM Application Guide

It is recommended to use an ESD protection component such as ESDA6V1W5 produced by ST ([www.st.com](http://www.st.com)) or SMF15C produced by ON SEMI ([www.onsemi.com](http://www.onsemi.com)). Note that the USIM peripheral circuit should be close to the USIM card socket. The following figure shows the 6-pin SIM card holder reference circuit.

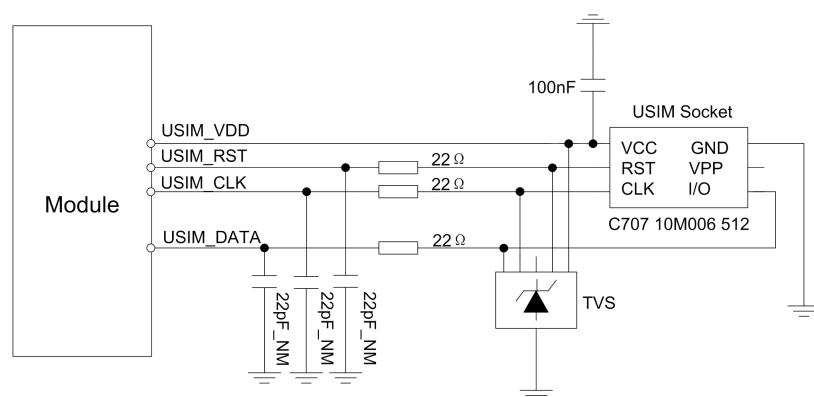


Figure 25: USIM Interface Reference Circuit

### NOTE

1. USIM\_DATA has been pulled up with a 10 KΩ resistor to USIM\_VDD in module. A 100 nF capacitor on USIM\_VDD is used to reduce interference.
2. For more details of AT commands about USIM, please refer to document [1]. USIM\_CLK is very important signal, the rise time and fall time of USIM\_CLK should be less than 40ns, otherwise the USIM card might not be initialized correctly.

The USIM\_DET pin is used for detection of the USIM card hot plug in. User can select the 8-pin USIM card holder to implement USIM card detection function.

The following figure shows the 8-pin SIM card holder reference circuit.

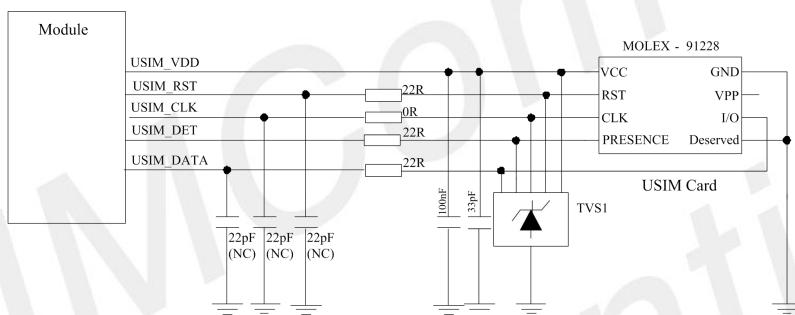


Figure 26: USIM Interface Reference Circuit with USIM\_DET

If the USIM card detection function is not used, user can keep the USIM\_DET pin open.

### 3.6.2 USIM Design Notice

USIM card circuit is susceptible; the interference may cause the SIM card failures or some other situations, so it is strongly recommended to follow these guidelines while designing:

- Make sure that the SIM card holder should be far away from the antenna while in PCB layout.
- SIM traces should keep away from RF lines, VBAT and high-speed signal lines.
- The traces should be as short as possible.
- Keep SIM holder's GND connect to main ground directly.
- Shielding the SIM card signal by ground.
- Recommended to place a 0.1~1 uF capacitor on USIM\_VDD line and keep close to the holder.
- The rise/fall time of USIM\_CLK should not be more than 40ns.
- Add some TVS and the parasitic capacitance should not exceed 60pF.

### 3.6.3 Recommended USIM Card Holder

It is recommended to use the 6-pin USIM socket such as C707 10M006 512 produced by Amphenol. User can visit <http://www.amphenol.com> for more information about the holder.

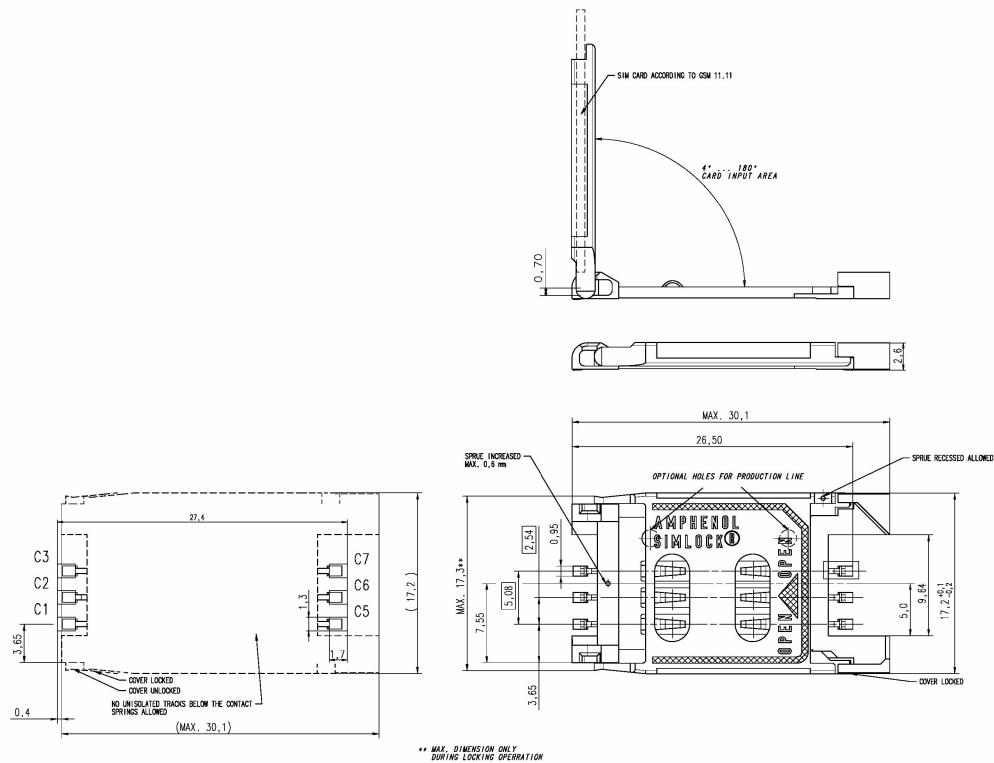


Figure 27: Amphenol SIM Card Socket

Table 19: Amphenol USIM Socket Pin Description

Pin	Signal	Description
C1	USIM_VDD	USIM Card Power supply.
C2	USIM_RST	USIM Card Reset.
C3	USIM_CLK	USIM Card Clock.
C5	GND	Connect to GND.
C6	VPP	
C7	USIM_DATA	USIM Card data I/O.

### 3.7 PCM Interface

Module provides a PCM interface for external codec, which can be used in master mode with short sync and 16 bits linear format.

Table 20: PCM Format

Characteristics	Specification
Line Interface Format	Linear(Fixed)
Data length	16bits(Fixed)
PCM Clock/Sync Source	Master Mode(Fixed)
PCM Clock Rate	2048kHz (2G/3G) ,4096Khz (4G)
PCM Sync Format	Short sync(Fixed)
Data Ordering	MSB

### NOTE

For more details about PCM AT commands, please refer to document [1].

#### 3.7.1 PCM Timing

Module supports 2.048 MHz PCM data and sync timing for 16 bits linear format codec.

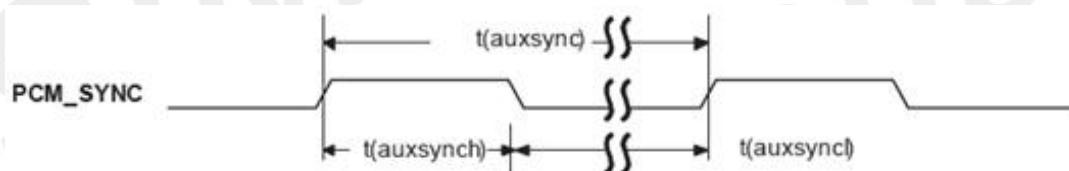


Figure 28: PCM\_SYNC Timing

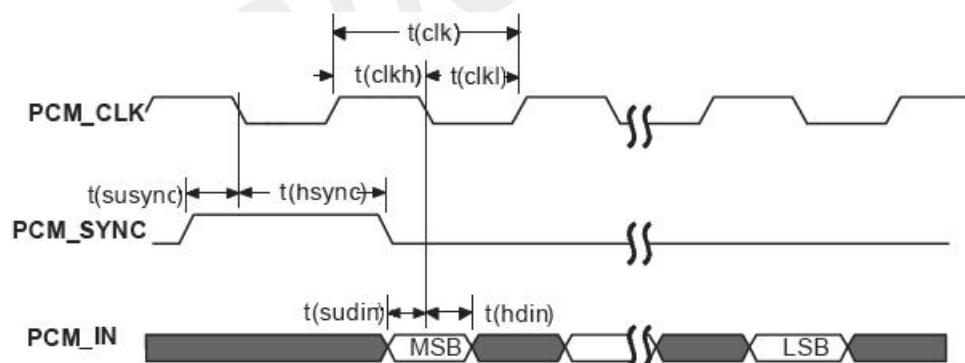


Figure 29: EXT Codec to Module Timing

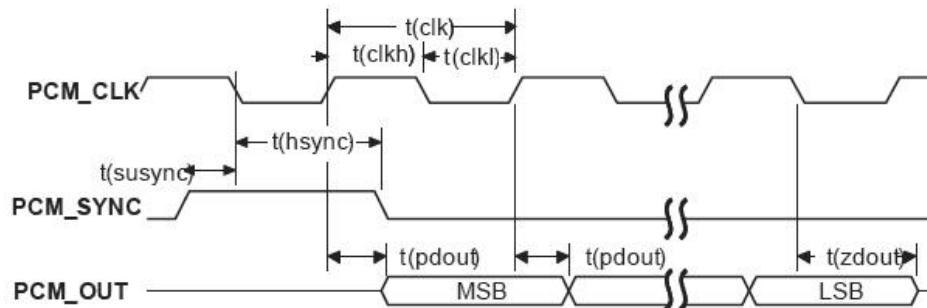


Figure 30: Module to Codec Timing

Table 21: PCM Timing Parameters (2G/3G mode)

Symbol	Parameter	Min.	Typ.	Max.	Unit
T(sync)	PCM_SYNC cycle time	–	125	–	μs
T(synch)	PCM_SYNC high level time	–	488	–	ns
T(syncl)	PCM_SYNC low level time	–	124.5	–	μs
T(clk)	PCM_CLK cycle time	–	488	–	ns
T(clkh)	PCM_CLK high level time	–	244	–	ns
T(clkl)	PCM_CLK low level time	–	244	–	ns
T(susync)	PCM_SYNC setup time high before falling edge of PCM_CLK	–	244	–	ns
T(hsync)	PCM_SYNC hold time after falling edge of PCM_CLK	–	244	–	ns
T(sudin)	PCM_IN setup time before falling edge of PCM_CLK	60	–	–	ns
T(hdin)	PCM_IN hold time after falling edge of PCM_CLK	10	–	–	ns
T(pdout)	Delay from PCM_CLK rising to PCM_OUT valid	–	–	60	ns
T(zdout)	Delay from PCM_CLK falling to PCM_OUT HIGH-Z	–	160	–	ns

Table 22: PCM Timing Parameters (4G mode)

Symbol	Parameter	Min.	Typ.	Max.	Unit
T(sync)	PCM_SYNC cycle time	–	62.5	–	μs
T(synch)	PCM_SYNC high level time	–	244	–	ns
T(syncl)	PCM_SYNC low level time	–	62.256	–	μs
T(clk)	PCM_CLK cycle time	–	244	–	ns
T(clkh)	PCM_CLK high level time	–	122	–	ns
T(clkl)	PCM_CLK low level time	–	122	–	ns
T(susync)	PCM_SYNC setup time high before falling edge of PCM_CLK	–	122	–	ns
T(hsync)	PCM_SYNC hold time after falling edge of	–	122	–	ns

	PCM_CLK					
T(sudin)	PCM_IN setup time before falling edge of PCM_CLK	122	—	—	ns	
T(hdin)	PCM_IN hold time after falling edge of PCM_CLK	122	—	—	ns	
T(pdout)	Delay from PCM_CLK rising to PCM_OUT valid	—	—	122	ns	
T(zdout)	Delay from PCM_CLK falling to PCM_OUT HIGH-Z	—	—	122	ns	

### 3.7.2 PCM Application Guide

The following figure shows the external codec reference design.

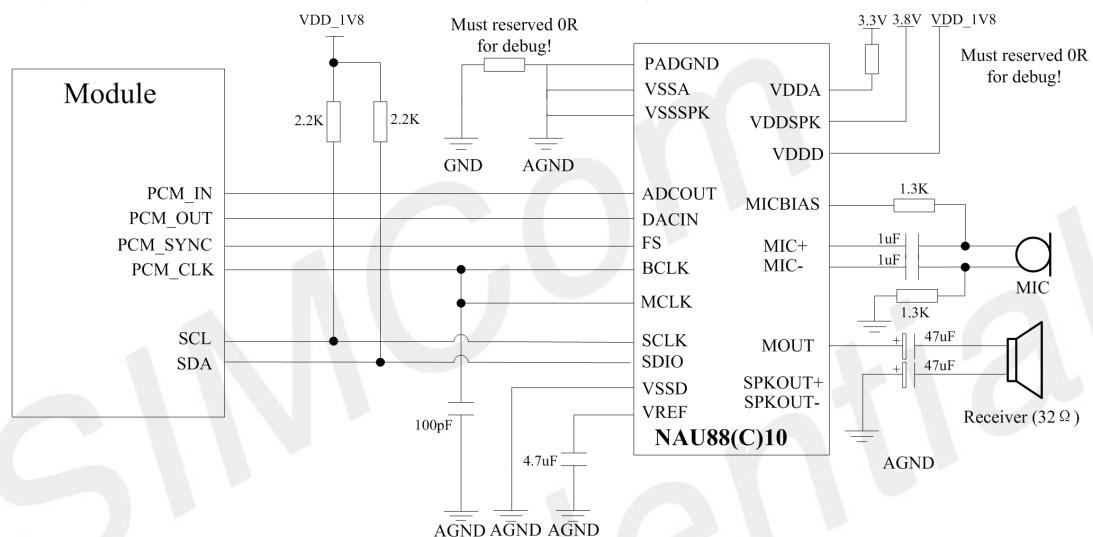


Figure 31: Audio Codec Reference Circuit

#### NOTE

This function is still in developing.

### 3.8 GPIO Interfaces

Table 23: GPIO Resources

PIN No	PIN Name	Int	Power Domain	Default Status
33	WL_PWR_EN/GPIO11	✓	P3	PD
34	I2S_MCLK/GPIO12	✓	P3	PD
45	GPIO13	✓	P3	PU
49	WL_PDN	✓	P3	PU
73	GPIO24/PCM_OUT	✓	P3	PD
74	GPIO25/PCM_IN	✓	P3	PD

75	GPIO26/PCM_SYNC	✓	P3	PD
76	GPIO27/PCM_CLK	✓	P3	PD
119	GPIO04	✓	P3	PU

### 3.9 SD Interface

Module provides a 4-bit SD/MMC interface with clock rate up to 200 MHz, The voltage of MMC/SD interface is 3.0 V, which is compatible with SDIO Card Specification (version 3.0) and Secure Digital (Physical Layer Specification, version 3.0). It supports up to 32GB SD cards.

**Table 24: 3.0V IO MMC/SD Electronic Characteristic (SD\_DATA0-SD\_DATA3,SD\_CLK and SD\_CMD)**  
\*

Symbol	Parameter	Min.	Typ.	Max.	Unit
V <sub>IH</sub>	High-level input voltage	2	-	3.6	V
V <sub>IL</sub>	Low-level input voltage	-0.3	0	0.8	V
V <sub>OH</sub>	High-level output voltage	2.4	-	-	V
V <sub>OL</sub>	Low-level output voltage	0	-	0.4	V

**Table 25: 1.8V IO MMC/SD Electronic Characteristic (SD\_DATA0-SD\_DATA3,SD\_CLK and SD\_CMD)**  
\*

Symbol	Parameter	Min.	Typ.	Max.	Unit
V <sub>IH</sub>	High-level input voltage	1.26	1.8	2.0	V
V <sub>IL</sub>	Low-level input voltage	-0.3	0	0.8	V
V <sub>OH</sub>	High-level output voltage	2.4	-	-	V
V <sub>OL</sub>	Low-level output voltage	0	-	0.4	V

#### NOTE

SD\_DET is 1.8 V operation voltage ,which is different from SD\_DATA0-SD\_DATA3,SD\_CLK and SD\_CMD.

Users should provide 2.85 V to power SD card system and the current should more than 500 mA, which is showed below as VDD\_SD. ESD/EMI components should be arranged beside SD card socket. Refer to the following application circuit.

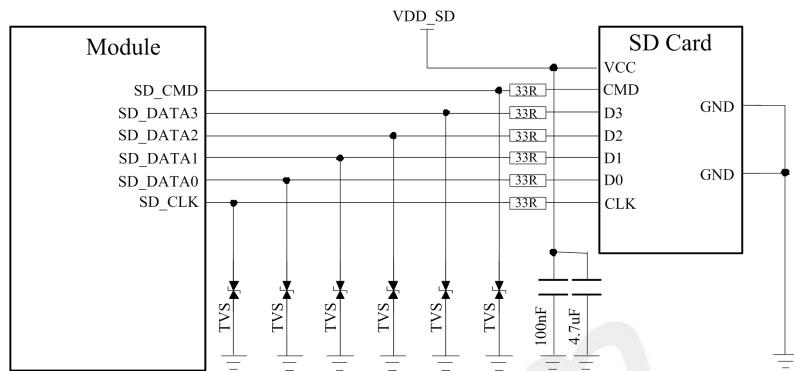


Figure 32: SD Reference Circuit

SD card layout guide lines:

- Protect other sensitive signals/circuits from SD card signals
- Protect SD card signals from noisy signals (clocks, SMPS, etc.)
- Up to 200 MHz clock rate, 50 Ω nominal, ±10% trace impedance
- CLK to DATA/CMD length matching < 1 mm
- 15–24 Ω termination resistor on clock lines near module
- Total routing length < 50 mm recommended
- Routing distance from module clock pin to termination resistor < 5 mm
- Spacing to all other signals = 2x line width
- Bus capacitance < 15 pF

### 3.10 I2C Interface

Module provides a I2C interface compatible with I2C specification, version 5.0, with clock rate up to 400 kbps. Its operation voltage is 1.8 V.

The following figure shows the I2C bus reference design.

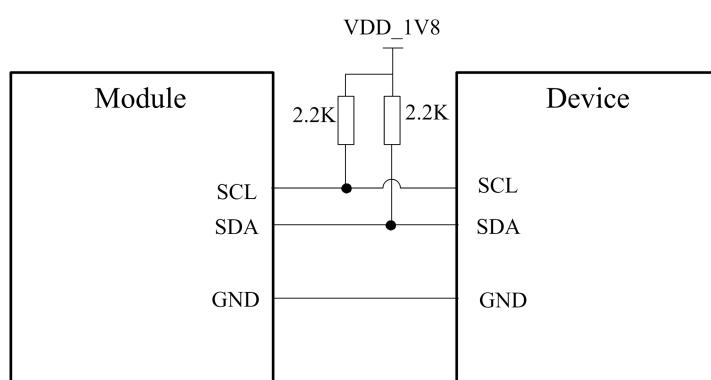


Figure 33: I2C Reference Circuit

**NOTE**

SDA and SCL do not have pull-up resistors in module. So, 2 externals pull up resistors are needed in application circuit.

### 3.11 SDIO Interface

Module provides a 4 bit 1.8 V SDIO interface for WLAN solution.

**Table 26: WIFI Interface**

PIN No	PIN Name	I/O	Power Domain	Function Description	Index
27	SDIO_DATA1	IO	P3	SDIO data bus bit1	
28	SDIO_DATA2	IO	P3	SDIO data bus bit2	
29	SDIO_CMD	IO	P3	SDIO bus command	
30	SDIO_DATA0	IO	P3	SDIO data bus bit0	
31	SDIO_DATA3	IO	P3	SDIO data bus bit3	
32	SDIO_CLK	DO	P3	SDIO bus clock	
49	WL_PDN	DO	P3	WIFI enable signal	
33	WL_PWR_EN	DO	P3	WIFI power enable	

### 3.12 SPI Interface

Module provides a SPI interface as a master only. Its operation voltage is 1.8 V, and its clock rate is up to 50 MHz.

### 3.13 Network Status

The NETLIGHT pin is used to control Network Status LED, its reference circuit is shown in the following figure.

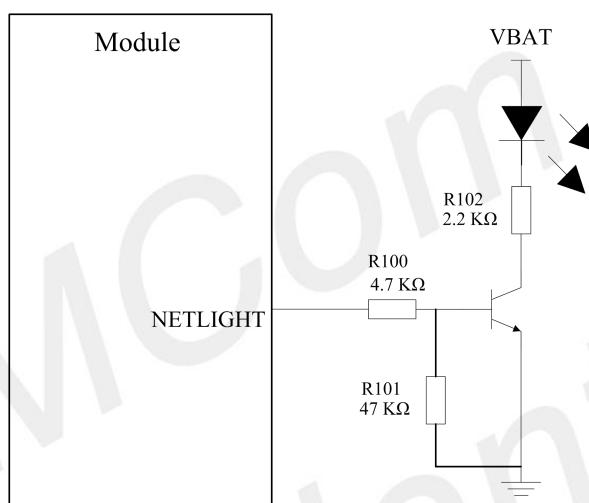


Figure 34: NETLIGHT Reference Circuit

#### NOTE

The value of the resistor named “R” depends on the LED characteristic.

Table 27: NETLIGHT Status

NETLIGHT pin status	Module status
Always On	Searching Network; Call Connect (include VOLTE,SRLTE)
200 ms ON, 200 ms OFF	Data Transmit; 4G registered;
800 ms ON, 800 ms OFF	2G/3G registered network
OFF	Power off; Sleep

#### NOTE

NETLIGHT output low level as “OFF”, and high level as “ON”.

### 3.14 Flight Mode Control

The FLIGHTMODE pin can be used to control module to enter or exit the Flight mode. In Flight mode, the RF circuit is closed to prevent interference with other equipment and minimize current consumption. Bidirectional ESD protection component is suggested to add on FLIGHTMODE pin, its reference circuit is shown in the following figure.

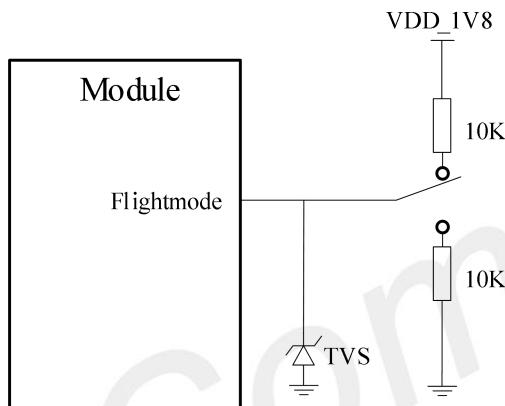


Figure 35: Flight Mode Switch Reference Circuit

Table 28: FLIGHTMODE Status

FLIGHTMODE pin status	Module operation
Input Low Level	Flight Mode: RF is closed
Input High Level	AT+CFUN=4: RF is closed AT+CFUN=1: RF is working

### 3.15 RMII Interface

Module provides one RMII Interface, Customers can design 100m network port based on this interface. 1.8V OR 3.3V need power supply for PIN159 Depending on PHY type.

Table 29: RMII interface

Pin Name	Pin No.	I/O	电压域	功能描述	信号名称
34	MAC_RST	DO	P6	Reset signal	
120	MAC_MDC	DO	P6	Management Data Clock	
125	MAC_MDO	IO	P6	Management Data Input/Output	
126	RMII_TX_EN	DO	P6	Transmit Enable	
127	RMII_RX_DV	DI	P6	Receive Data Valid	
128	RMII_CLK	DI	P6	RMII Clock	
129	RMII_INT	DI	P6	PHY interrupt output	
160	RMII_TXD1	DO	P6	Transmit Data [1]	
161	RMII_TXD0	DO	P6	Transmit Data [0]	
162	RMII_RXD0	DI	P6	Receive Data [0]	

163

RMII\_RXD1 DI P6

Receive Data [1]

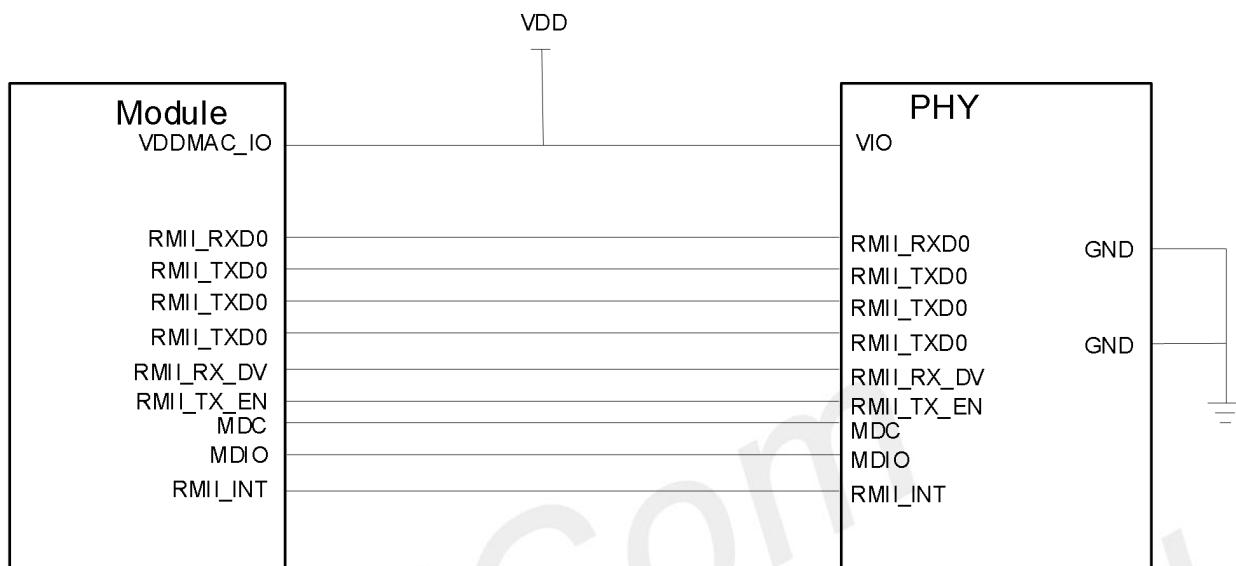


Figure 36: RMII Circuit Diagram

### 3.16 PCIe Interface\*

Module provides 1 lane PCIe Gen1 interface, Only support host mode (RC mode), the maximum data rate could up to 2.5 Gbps.

Feature:

- PCI Express® Base Specification Revision 3.1 compliant
- 32-bit PIPE interface, PIPE3.0 compliant
- Support 100 MHz differential reference clock, either with SSC or not
- SRIS (separate reference independent SSC) support
- Advanced Error Reporting (AER) support
- ECRC generation and check support
- Legacy PCI Power Management support
- Native Active State Power Management L0s and L1 state support
- Both WAKE# and beacon detection are supported
- MSI (up to 32) and INT message support
- Four reconfigurable DMA channels: 2 write and 2 read channels
- Up to 8 reconfigurable address translation tables for PCIe interface

### 3.17 GNSS Control Interface

The GNSS function is optional.

The GNSS is a stand-alone function, the module integrated GNSS chip, and module provide VGNSS pin, customer provide a 1.8 V voltage for VGNSS and the GNSS function is started, the GNSS\_TXD and GNSS\_RXD will provide NMEA sentences, customer could connect GNSS\_UART to UART2 to module, so the GNSS NMEA information could be handled by module, the GNSS\_UART also could connect to host side for other usage.

If customer need the GNSS in low power mode, customer could cut off the VGNSS power.

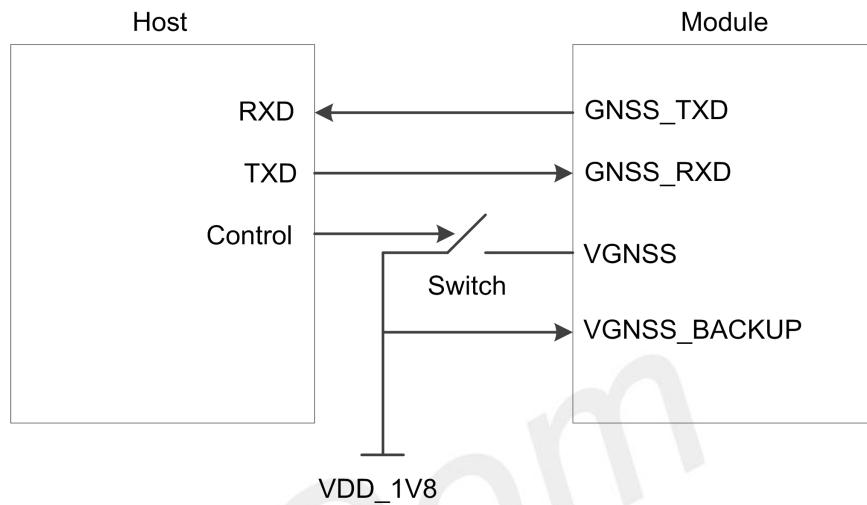


Figure 37: GNSS Circuit Diagram (NMEA to host UART)

## 3.18 Other Interface

### 3.18.1 ADC

The module has a dedicated ADC named ADC1. It is available for digitizing analog signals such as battery voltage and so on. These electronic specifications are shown in the following table.

Table 30: ADC1 Electronic Characteristics

Characteristics	Min.	Typ.	Max.	Unit
Resolution	—	15	—	Bits
Conversion time	—	442	—	us
Input Range	0.1	—	1.8	V
Input serial resistance	1	—	—	MΩ

**NOTE**

“AT+CADC=2” can be used to read the voltage, for more details, please refer to document [1].

### 3.18.2 LDO

Module has a LDO power output, named VDD\_AUX. its output voltage is 2.8 V by default, Users can switch the LDO on or off by the AT command “AT+CVAUXS”.

Table 31: LDO Electronic Characteristic

Symbol	Description	Min.	Typ.	Max.	Unit
V <sub>VDD_AUX</sub>	Output voltage	-	2.80	-	V
I <sub>O</sub>	Output current	-	-	150	mA

**NOTE**

For more details of AT commands about VDD\_AUX, please refer to document [1].

## 4 RF Specifications

### 4.1 GSM/UMTS/LTE RF Specifications

Table 32: GSM/UMTS/LTE Conducted Transmission Power

Frequency	Power	Min
GSM850	33dBm ±2 dB	5dBm ± 5 dB
EGSM900	33dBm ±2 dB	5dBm ± 5 dB
DCS1800	30dBm ±2 dB	0dBm ± 5 dB
PCS1900	30dBm ±2 dB	0dBm ± 5 dB
GSM850 (8-PSK)	27dBm ±3 dB	5dBm ± 5 dB
EGSM900 (8-PSK)	27dBm ±3 dB	5dBm ± 5 dB
DCS1800 (8-PSK)	26dBm +3/-4 dB	0dBm ±5 dB
PCS1900 (8-PSK)	26dBm +3/-4 dB	0dBm ±5 dB
WCDMA B1	24dBm +1/-3 dB	<-50 dBm
WCDMA B2	24dBm +1/-3 dB	<-50 dBm
WCDMA B5	24dBm +1/-3 dB	<-50 dBm
WCDMA B8	24dBm + 1/-3 dB	<-50 dBm
LTE-FDD B1	23dBm +/-2.7 dB	<-40 dBm
LTE-FDD B3	23dBm +/-2.7 dB	<-40 dBm
LTE-FDD B4	23dBm +/-2.7 dB	<-40 dBm
LTE-FDD B5	23dBm +/-2.7 dB	<-40 dBm
LTE-FDD B7	23dBm +/-2.7 dB	<-40 dBm
LTE-FDD B8	23dBm +/-2.7 dB	<-40 dBm
LTE-FDD B12	23dBm +/-2.7 dB	<-40 dBm
LTE-FDD B13	23dBm +/-2.7 dB	<-40 dBm
LTE-FDD B18	23dBm +/-2.7 dB	<-40 dBm
LTE-FDD B19	23dBm +/-2.7 dB	<-40 dBm
LTE-FDD B20	23dBm +/-2.7 dB	<-40 dBm
LTE-FDD B26	23dBm +/-2.7 dB	<-40 dBm
LTE-FDD B28	23dBm +/-2.7 dB	<-40 dBm
LTE-TDD B38	23dBm +/-2.7 dB	<-40 dBm
LTE-TDD B40	23dBm +/-2.7 dB	<-40 dBm
LTE-TDD B41	23dBm +/-2.7 dB	<-40 dBm

Table 33: Operating Frequencies

Frequency	Receiving	Transmission
GSM850	869 ~ 894 MHz	824 ~ 849 MHz
EGSM900	925 ~ 960 MHz	880 ~ 915 MHz
DCS1800	1805 ~ 1880 MHz	1710 ~ 1785 MHz
PCS1900	1930~1990 MHz	1850~1910 MHz
WCDMA B1	2110 ~ 2170 MHz	1920 ~ 1980 MHz
WCDMA B2	1930~1990 MHz	1850~1910 MHz
WCDMA B5	869 ~ 894 MHz	824 ~ 849 MHz
WCDMA B8	925 ~ 960 MHz	880 ~ 915 MHz

The LTE Operating frequencies are shown in the following table 24.

Note: Operating frequencies of LTE TDD B41 for the module is 100MHz BW, 2555 ~ 2655 MHz

GPS	1574.4 ~ 1576.44 MHz	-
GLONASS	1598 ~ 1606 MHz	-
BD	1559 ~ 1563 MHz	

Table 34: E-UTRA Operating Bands

E-UTRA Band	Uplink (UL)	Downlink (DL)
LTE-FDD B1	1920 ~1980 MHz	2110 ~2170 MHz
LTE-FDD B2	1850~1910 MHz	1930~1990 MHz
LTE-FDD B3	1710 ~1785 MHz	1805 ~1880 MHz
LTE-FDD B4	1710~1755 MHz	2110~2155 MHz
LTE-FDD B5	824 ~ 849 MHz	869 ~ 894 MHz
LTE-FDD B7	2500~2570 MHz	2620~2690 MHz
LTE-FDD B8	880 ~915 MHz	925 ~960 MHz
LTE-FDD B12	699~716 MHz	728~746 MHz
LTE-FDD B13	777~787 MHz	746~757 MHz
LTE-FDD B18	815~830 MHz	860~875 MHz
LTE-FDD B19	830~845 MHz	875~890 MHz
LTE-FDD B20	832~862 MHz	791~ 821 MHz
LTE-FDD B26	814~849 MHz	859~894 MHz
LTE-FDD B28	703~748 MHz	758~803 MHz
LTE-TDD B38	2570 ~2620 MHz	2570 ~2620 MHz
LTE-TDD B40	2300 ~2400 MHz	2300 ~2400 MHz
LTE-TDD B41	2496 ~2690 MHz	2496 ~2690 MHz

**Table 35: Conducted Receive Sensitivity**

Frequency	Receive sensitivity (Typical)	Receive sensitivity (MAX)
GSM850	< -109 dBm	3GPP
EGSM900	< -109 dBm	3GPP
DCS1800	< -109 dBm	3GPP
PCS1900	< -109 dBm	3GPP
WCDMA B1	< -110 dBm	3GPP
WCDMA B2	< -110 dBm	3GPP
WCDMA B5	< -110 dBm	3GPP
WCDMA B8	< -110 dBm	3GPP
LTE FDD/TDD	See table 26.	3GPP

**Table 36: Reference Sensitivity (QPSK)**

E-UTRA band	Standard						Test Value @10 MHz
	1.4 MHz	3 MHz	5 MHz	10 MHz	15 MHz	20 MHz	
LTE-FDD B1	-	-	-100	-97	-95.2	-94	-101
LTE-FDD B2	-102.7	-99.7	-98	-95	-93.2	-92	-99
LTE-FDD B3	-101.7	-98.7	-97	-94	-92.2	-91	-99
LTE-FDD B4	-104.7	-101.7	-100	-97	-95.2	-94	-101
LTE-FDD B5	-103.2	-100.2	-98	-95			-99
LTE-FDD B7			-98	-95	-93.2	-92	-97
LTE-FDD B8	-102.2	-99.2	-97	-94			-102
LTE-FDD B12	-101.7	-98.7	-97	-94			-99
LTE-FDD B13			-97	-94			-99
LTE-FDD B18			-100	-97	-95.2		-101
LTE-FDD B19			-100	-97	-95.2		-101
LTE-FDD B20			-97	-94	-91.2	-90	-98
LTE-FDD B26	-102.7	-99.7	-97.5	-94.5	-92.7		-99
LTE-FDD B28		-100.2	-98.5	-95.5	-93.7	-91	-99
LTE-TDD B38	-	-	-100	-97	-95.2	-94	-101
LTE-TDD B40	-	-	-100	-97	-95.2	-94	-101
LTE-TDD B41	-	-	-99	-96	-94.2	-93	-101

## 4.2 GSM /UMTS/LTE Antenna Design Guide

Users should connect antennas to module's antenna pads through micro-strip line or other types of RF trace and the trace impedance must be controlled in  $50\ \Omega$ . SIMCom recommends that the total insertion loss between the antenna pads and antennas should meet the following requirements:

**Table 37: Trace Loss**

Frequency	Loss
700 MHz-960 MHz	<0.5 dB
1710 MHz-2170 MHz	<0.9 dB
2300 MHz-2650 MHz	<1.2 dB

To facilitate the antenna tuning and certification test, a RF connector and an antenna matching circuit should be added. The following figure is the recommended circuit.

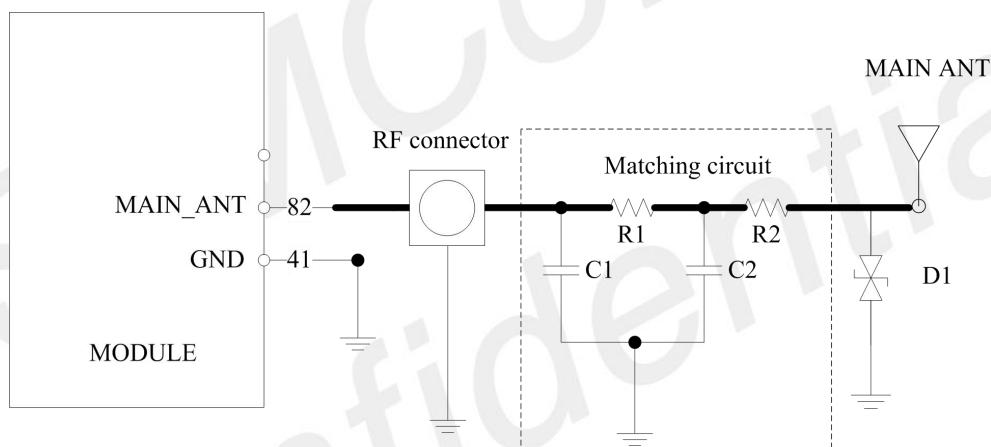


Figure 38: Antenna Matching Circuit (MAIN\_ANT)

In above figure, the components R1, C1, C2 and R2 are used for antenna matching, the values of components can only be achieved after the antenna tuning and usually provided by antenna vendor. By default, the R1, R2 are  $0\ \Omega$  resistors, and the C1, C2 are reserved for tuning. The component D1 is a TVS for ESD protection, and it is optional for users according to application environment.

The RF test connector is used for the conducted RF performance test, and should be placed as close as to the module's MAIN\_ANT pin. The traces impedance between module and antenna must be controlled in  $50\ \Omega$ .

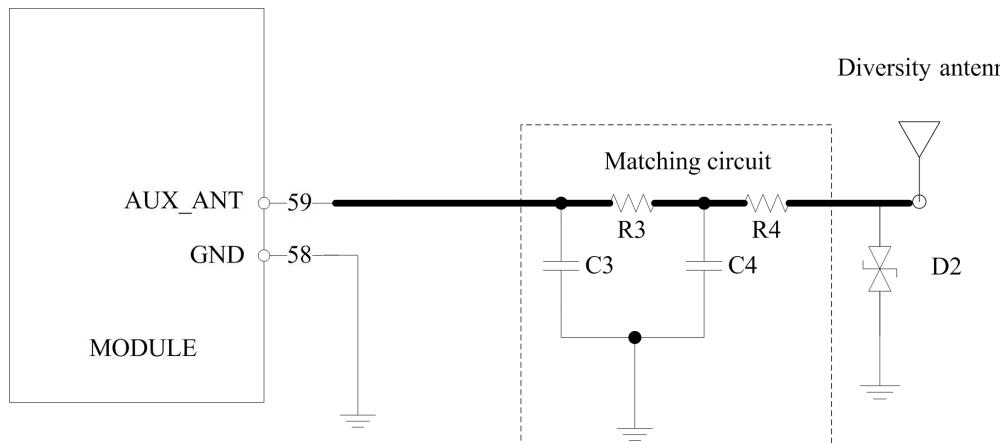


Figure 39: Antenna Matching Circuit (AUX\_ANT)

In above figure, R3, C3, C4 and R4 are used for auxiliary antenna matching. By default, the R3, R4 are  $0\Omega$  resistors, and the C3, C4 are reserved for tuning. D2 is a TVS for ESD protection, and it is optional for users according to application environment.

Two TVS are recommended in the table below.

Table 38: Recommended TVS

Package	Part Number	Vender
0201	WE05DGCM-S-BH	CYGWAYON
0402	PESD0402-03	PRISEMI
0402	PESD0402-12	PRISEMI

**NOTE**

SIMCom suggests the LTE auxiliary antenna to be kept on, since there are many high bands in the designing of LTE-TDD, such as band38, band40 and band41. Because of the high insert loss of the RF cable and layout lines, the receiver sensitivity of these bands above will have risk to meet the authentication without the diversity antenna. For more details about auxiliary antenna design notice, please refer to document [25].

## 4.3 GNSS

Module merges GNSS (GPS/GLONASS/BD/QZSS GALILEO) satellite and network information to provide a high-availability solution that offers industry-leading accuracy and performance. This solution performs well, even in very challenging environmental conditions where conventional GNSS receivers fail, and provides a platform to enable wireless operators to address both location-based services and emergency mandates.

### 4.3.1 GNSS Technical Specification

- Tracking sensitivity: -159 dBm ( GPS ) /-158 dBm ( GLONASS ) /-159 dBm ( BD ) /-159 dBm ( GALILEO )
- Cold-start sensitivity: -148 dBm
- Accuracy (Open Sky): 2.5 m (CEP50)
- TTFF (Open Sky): Hot start <1 s, Cold start<35 s
- Receiver Type: 16-channel, C/A Code
- GPS L1 Frequency:  $1575.42 \pm 1.023$  MHz
- GLONASS: 1597.5~1605.8 MHz
- BD: 1559.05~1563.14 MHz
- GALILEO:  $1575.42 \pm 1.023$  MHz
- Update rate: Default 1 Hz
- GNSS data format: NMEA-0183
- GNSS Current consumption: 100mA (GSM/UMTS/LTE Sleep ,in total on VBAT pins)
- GNSS antenna: Passive/Active antenna

Table 39: Recommended Passive Antenna Characteristics

Passive	Recommended standard
Direction	Omnidirectional
Gain	>-3 dBi ( Avg )
Input impedance	50 Ω
Efficiency	>50%
VSWR	<2

#### NOTE

If the antenna is active type, the power should be given by main board because there is no power supply on the GPS antenna pad. If the antenna is passive, it is suggested that the external LNA should be used.

#### 4.3.2 GNSS Application Guide

Users can adopt an active antenna or a passive antenna to module. If using a passive antenna, an external LNA is a must to get better performance.

The following figures are the reference circuits.

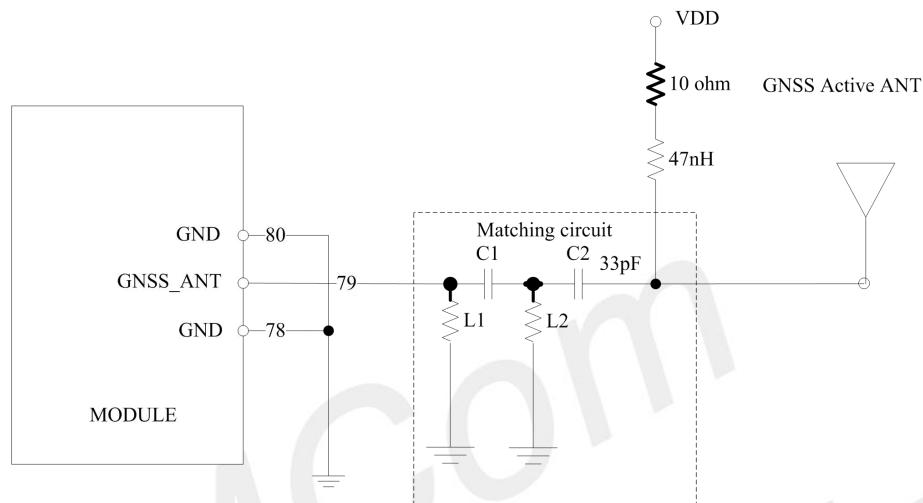


Figure 40: Active Antenna Circuit

#### NOTE

If customer need save the power when the GNSS function is disabled, then customer should design a switch circuit to cut off the active antenna power to get a lower power consumption.

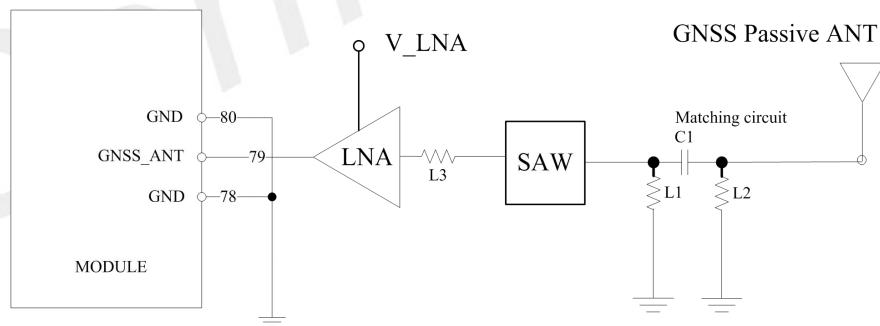


Figure 41: Passive Antenna Circuit (Default)

In above figures, the components C1, L1 and L2 are used for antenna matching. Usually, the values of the components can only be achieved after antenna tuning and usually provided by antenna vendor. C2 is used for DC blocking. L3 is the matching component of the external LNA, and the value of L3 is determined by the LNA characteristic and PCB layout. Both VDD of active antenna and V\_LNA need external power supplies which should be considered according to active antenna and LNA characteristic. LDO/DCDC is recommended to get lower current consuming by shutting down active antennas and LNA when GNSS is not working.

Table 40: Recommended LNA and SAW Filter

Material	Part Number	Vendor
GPS LNA	MXDLN16TP	MAXSCEND
GPS LNA	BGA725L6	Infineon
GPS LNA	BGA824N6	Infineon
GPS SAW FILTER	HDF1588E-B5	SHOULDER
GPS SAW FILTER	SAFFB1G56KB0F0A	murata

GNSS can be tested by NMEA port. NMEA sentences can be obtained through UART or USB automatically. NMEA sentences include GSV, GGA, RMC, GSA, and VTG. Before using GNSS, user should configure module in proper operating mode by AT command. Please refer to related documents for details. module can also get position location information through AT directly.

**NOTE**

GNSS is closed by default and can be started by AT+CGPS. The AT command has two parameters, the first is on/off, and the second is GNSS mode. Default mode is standalone mode.

AGPS mode needs more support from the mobile telecommunication network. Please refer to document [24] for more details.

## 5 Electrical Specifications

### 5.1 Absolute Maximum Ratings

Absolute maximum ratings for digital and analog pins of module are listed in the following table.

Table 41: Absolute Maximum Ratings

Parameter	Min.	Typ.	Max.	Unit
Voltage at VBAT	-0.3	-	6	V
Voltage at USB_VBUS	-0.5	-	5.5	V
Voltage at digital pins (RESET, SPI, Keypad, GPIO, I2C, UART, PCM)	-0.3	-	2.1	V
Voltage at digital pins (SD, USIM)	-0.3	-	3.3	V
Voltage at PWRKEY	-0.3	-	6	V

### 5.2 Operating Conditions

Table 42: Recommended Operating Ratings

Parameter	Min.	Typ.	Max.	Unit
Voltage at VBAT	3.4	3.8	4.2	V
Voltage at USB_VBUS	3.6	5.0	5.25	V

Table 43: 1.8V Digital I/O Characteristics\*

Parameter	Description	Min.	Typ.	Max.	Unit
$V_{IH}$	High-level input voltage	1.26	1.8	2	V
$V_{IL}$	Low-level input voltage	-0.3	0	0.54	V
$V_{OH}$	High-level output voltage	1.6	-	-	V
$V_{OL}$	Low-level output voltage	0	-	0.2	V
$I_{OH}$	High-level output current (no pull-down resistor)	-	2	-	mA
$I_{OL}$	Low-level output current (no pull up resistor)	-	-2	-	mA
$I_{IH}$	Input high leakage current (no pull-down resistor)	-	-	1	uA
$I_{IL}$	Input low leakage current (no pull up resistor)	-1	-	-	uA

**NOTE**

These parameters are for digital interface pins, such as SPI, GPIO (NETLIGHT, FLIGHTMODE, STATUS, USIM\_DET, SD\_DET), I2C, UART, PCM, and USB\_BOOT.

The operating temperature of module is listed in the following table.

**Table 44: Operating Temperature**

Parameter	Min.	Typ.	Max.	Unit
Normal operation temperature	-30	25	80	°C
Extended operation temperature*	-40	25	85	°C
Storage temperature	-45	25	+90	°C

**NOTE**

Module is able to make and receive voice calls, data calls, SMS and make GSM/ UMTX/LTE traffic in -40 °C ~ +85 °C . The performance will be reduced slightly from the 3GPP specifications if the temperature is outside the normal operating temperature range and still within the extreme operating temperature range.

## 5.3 Operating Mode

### 5.3.1 Operating Mode Definition

The table below summarizes the various operating modes of module product.

**Table 45: Operating Mode Definition**

Mode	Function
Normal operation	GSM /UMTS/LTE Sleep In this case, the current consumption of module will be reduced to the minimal level and the module can still receive paging message, call, SMS and TCP/UDP.
	GSM/UMTS/LTE Idle Software is active. Module is registered to the network, and the module is ready to communicate.
	GSM/UMTS/LTE Talk Connection between two subscribers is in progress. In this case, the power consumption depends on network settings such as DTX off/on, FR/EFR/HR, hopping sequences, and antenna.
	GPRS/EDGE/ UMTS/LTE Standby Module is ready for data transmission, but no data is currently sent or received. In this case, power consumption depends on network settings.
	GPRS/EDGE/ There is data transmission in progress. In this case, power

UMTS/LTE transmission	Data consumption is related to network settings (e.g. power control level); uplink/downlink data rates, etc.
Minimum functionality mode	AT command “AT+CFUN=0” AT+CSCLK=1 can be used to set the module to a minimum functionality mode without removing the power supply. In this mode, the RF part of the module will not work and the USIM card will not be accessible, but the serial port and USB port are still accessible. The power consumption in this mode is lower than normal mode.
Flight mode	AT command “AT+CFUN=4” or pulling down the FLIGHTMODE pin can be used to set the module to flight mode without removing the power supply. In this mode, the RF part of the module will not work, but the serial port and USB port are still accessible. The power consumption in this mode is lower than normal mode.
Power off	Module will go into power off mode by sending the AT command “AT+CPOF” or pull down the PWRKEY pin, normally. In this mode the power management unit shuts down the power supply, and software is not active. The serial port and USB are is not accessible.

### 5.3.2 Sleep Mode

In sleep mode, the current consumption of module will be reduced to the minimal level, and module can still receive paging message and SMS and TCP/UDP.

Several hardware and software conditions must be satisfied together in order to let module enter into sleep mode:

- UART condition
- USB condition
- Software condition

#### NOTE

Before designing, pay attention to how to realize sleeping/waking function and refer to Document [26] for more details.

### 5.3.3 Minimum Functionality Mode and Flight Mode

Minimum functionality mode ceases a majority function of module, thus minimizing the power consumption. This mode is set by the AT command which provides a choice of the functionality levels.

- AT+CFUN=0: Minimum functionality
- AT+CFUN=1: Full functionality (Default)
- AT+CFUN=4: Flight mode

If module has been set to minimum functionality mode, the RF function and USIM card function will be closed. In this case, the serial port and USB are still accessible, but RF function and USIM card will be unavailable.

If module has been set to flight mode, the RF function will be closed. In this case, the serial port and USB are still accessible, but RF function will be unavailable.

When module is in minimum functionality or flight mode, it can return to full functionality by the AT command "AT+CFUN=1".

## 5.4 Current Consumption

The current consumption is listed in the table below.

**Table 46: Current Consumption on VBAT Pins (VBAT=3.8V)**

<b>GNSS</b>	
GNSS supply current (AT+CFUN=0,without USB connection)	@ -140 dBm, Tracking Typical:35 mA
<b>GSM sleep/idle mode</b>	
GSM/GPRS supply current (GNSS off,without USB connection)	Sleep mode@ BS_PA_MFRMS=2 Typical: 2.8 mA Idle mode@ BS_PA_MFRMS=2 Typical: 18 mA
<b>UMTS sleep/idle mode</b>	
WCDMA supply current (GNSS off,without USB connection)	Sleep mode @DRX=9 Typical: 3.3 mA Idle mode @DRX=9 Typical: 17.5 mA
<b>LTE sleep/idle mode</b>	
LTE supply current (GNSS off,without USB connection)	Sleep mode Typical: 2.3 mA Idle mode Typical: 17.5 mA
EVDO supply current (GNSS off,without USB connection)	Sleep mode Typical: 2.0 mA Idle mode Typical: 17.8 mA
<b>GSM Talk</b>	
GSM850	@power level #5 Typical: 220 mA
EGSM900	@ power level #5 Typical: 230 mA
DCS1800	@power level #5 Typical: 16 2mA
PCS1900	@power level #5 Typical: 190 mA
<b>UMTS Talk</b>	
WCDMA B1	@Power 24 dBm Typical: 540 mA
WCDMA B2	@Power 24 dBm Typical: 470 mA
WCDMA B5	@Power 24 dBm Typical: 530 mA
WCDMA B8	@Power 24 dBm Typical: 385 mA
<b>GPRS</b>	
GSM850( 1 Rx,4 Tx )	@power level #5 Typical: 480 mA
EGSM900( 1 Rx,4 Tx )	@power level #5 Typical: 230 mA
DCS1800( 1 Rx,4 Tx )	@power level #0 Typical: 195 mA
PCS1900( 1 Rx,4 Tx )	@power level #0 Typical: 390 mA
GSM850( 3Rx, 2 Tx )	@power level #5 Typical: 330 mA
EGSM900( 3Rx, 2 Tx )	@power level #5 Typical: 370 mA
DCS1800( 3Rx, 2 Tx )	@power level #0 Typical: 275 mA
PCS1900( 3Rx, 2 Tx )	@power level #0 Typical: 245 mA
<b>EDGE</b>	

GSM850( 1 Rx,4 Tx )	@power level #8 Typical: 340 mA	
EGSM900( 1 Rx,4 Tx )	@power level #8 Typical: 400 mA	
DCS1800( 1 Rx,4 Tx )	@power level #2 Typical: 300 mA	
PCS1900( 1 Rx,4 Tx )	@power level #2 Typical: 330 mA	
GSM850( 3Rx, 2 Tx )	@power level #8 Typical: 280 mA	
EGSM900( 3Rx, 2 Tx )	@power level #8 Typical: 320 mA	
DCS1800( 3Rx, 2 Tx )	@power level #2 Typical: 230 mA	
PCS1900( 3Rx, 2 Tx )	@power level #2 Typical: 268 mA	
GSM850( 1 Rx,4 Tx )		
EGSM900( 1 Rx,4 Tx )	@power level #8 Typical: 400 mA	
DCS1800( 1 Rx,4 Tx )	@power level #2 Typical: 300 mA	

### HSDPA data

WCDMA B1	@Power 24 dBm	Typical: 478 mA
WCDMA B2	@Power 23 dBm	Typical: 475 mA
WCDMA B5	@Power 24 dBm	Typical: 480 mA
WCDMA B8	@Power 24 dBm	Typical: 430 mA

### LTE data

LTE-FDD B1	@5MHz 22.3 dBm	Typical: 577 mA
LTE-FDD B2	@10MHz 22.4 dBm	Typical: 590 mA
LTE-FDD B3	@20MHz 22.4 dBm	Typical: 630 mA
LTE-FDD B4	@5MHz 22.1 dBm	Typical: 515 mA
LTE-FDD B5	@10MHz 22.4 dBm	Typical: 544 mA
LTE-FDD B7	@20MHz 22.3 dBm	Typical: 575 mA
LTE-FDD B8	@5MHz 22.2 dBm	Typical: 479 mA
LTE-FDD B12	@10MHz 22.1 dBm	Typical: 498 mA
LTE-FDD B13	@20MHz 22.1 dBm	Typical: 530 mA
LTE-FDD B18	@5MHz 22.0 dBm	Typical: 527 mA
LTE-FDD B19	@10MHz 22.1 dBm	Typical: 559 mA
LTE-FDD B20	@20MHz 22.6 dBm	Typical: 555 mA
LTE-FDD B26	@5MHz 22.2 dBm	Typical: 610 mA
	@10MHz 22.1 dBm	Typical: 600 mA
	@20MHz 22.1 dBm	Typical: 630 mA
	@5MHz 22.2 dBm	Typical: 650 mA
	@10MHz 22.1 dBm	Typical: 650 mA
	@20MHz 22.1 dBm	Typical: 630 mA
	@5MHz 22.8 dBm	Typical: 644 mA
	@10MHz 22.8 dBm	Typical: 646 mA
	@5MHz 22.7 dBm	Typical: 493 mA
	@10MHz 22.7 dBm	Typical: 510 mA
	@5MHz 21.9 dBm	Typical: 505 mA
	@10MHz 22.0 dBm	Typical: 497 mA
	@5MHz 21.3 dBm	Typical: 531 mA
	@10MHz 22.5 dBm	Typical: 523 mA
	@15MHz 22.6 dBm	Typical: 570 mA
	@5MHz 22.4 dBm	Typical: 532 mA
	@10MHz 22.3 dBm	Typical: 541 mA
	@15MHz 22.5 dBm	Typical: 590 mA
	@5MHz 21.8 dBm	Typical: 579 mA
	@10MHz 21.8 dBm	Typical: 590 mA
	@20MHz 21.8 dBm	Typical: 600 mA
	@5MHz 22.4 dBm	Typical: 525 mA

LTE-FDD B28	@10MHz 22.7 dBm @15MHz 22.3 dBm @5MHz 22.4 dBm @10MHz 22.5 dBm @20MHz 22.4 dBm	Typical: 570 mA Typical: 580 mA Typical: 612 mA Typical: 510mA Typical: 670 mA
LTE-TDD B38	@5MHz 21.8 dBm @10MHz 21.8 dBm @20MHz 21.8 dBm	Typical: 370 mA Typical: 380 mA Typical: 403 mA
LTE-TDD B40	@5MHz 21.5 dBm @10MHz 21.7 dBm @20MHz 21.7 dBm	Typical: 407 mA Typical: 416 mA Typical: 444 mA
LTE-TDD B41	@5MHz 21.6 dBm @10MHz 21.7 dBm @20MHz 21.7 dBm	Typical: 390 mA Typical: 396 mA Typical: 420 mA

## 5.5 ESD Notes

Module is sensitive to ESD in the process of storage, transporting, and assembling. When module is mounted on the users' mother board, the ESD components should be placed beside the connectors which human body may touch, such as USIM card holder, audio jacks, switches, keys, etc. The following table shows the module ESD measurement performance without any external ESD component.

Table 47: The ESD Performance Measurement Table (Temperature: 25 °C, Humidity: 45%)

Part	Contact discharge	Air discharge	Part
VBAT, GND	+/-4 KV	+/-8 KV	VBAT, GND
Antenna port	+/-4 KV	+/-8 KV	Antenna port
USB	+/-1 KV	+/-2 KV	USB
UART	+/-1 KV	+/-2 KV	UART
Other PADs	+/-1 KV	+/-2 KV	Other PADs

## 6 SMT Production Guide

### 6.1 Top and Bottom View of Module

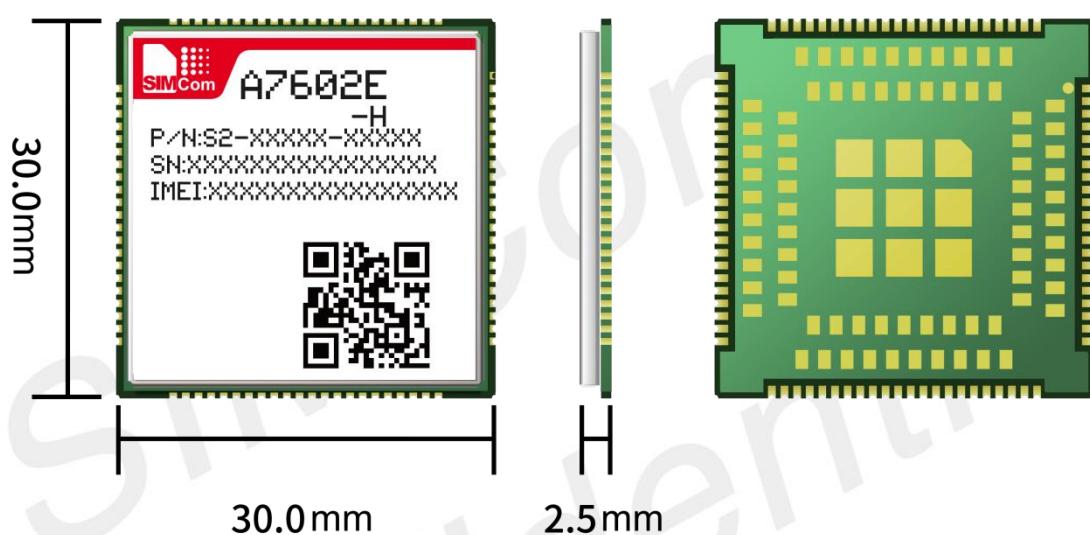


Figure 42: Top and Bottom View of Module

## 6.2 Label Information

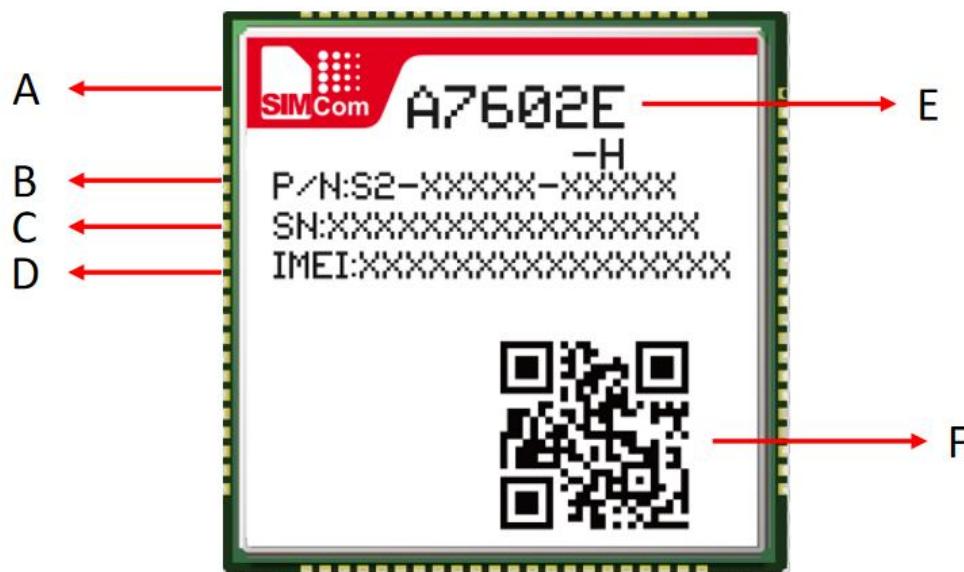


Figure 43: Label Information

Table 48: The Description of Label Information

No.	Description
A	LOGO
B	Module part number
C	Project name
D	Serial number
E	International mobile equipment identity
F	QR code

## 6.3 Typical SMT Reflow Profile

SIMCom provides a typical soldering profile. Therefore, the soldering profile shown below is only a generic recommendation and should be adjusted to the specific application and manufacturing constraints.

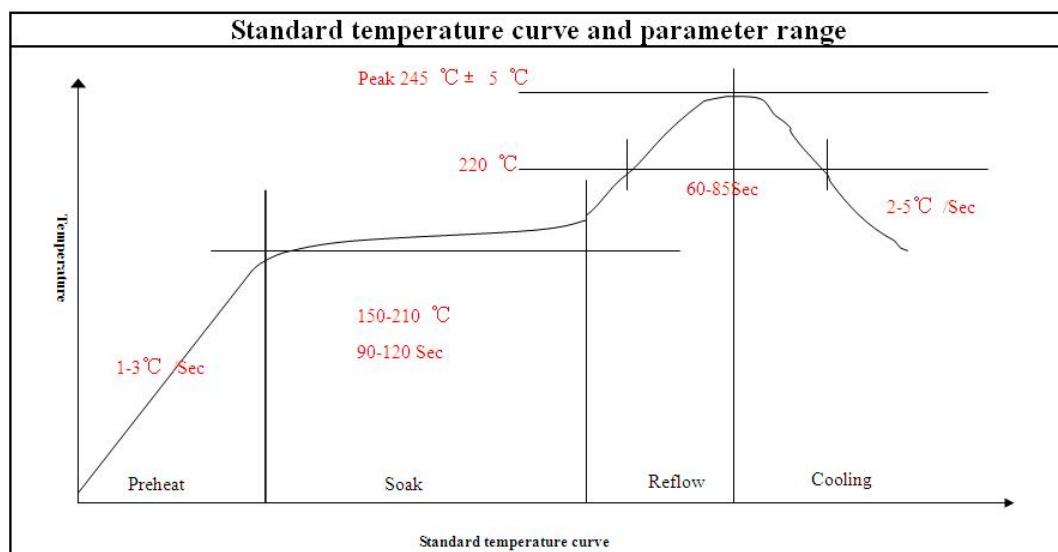


Figure 44: The Ramp-soak-spike Reflow Profile of Module

**NOTE**

For more details about secondary SMT, please refer to the document [21].

## 6.4 Moisture Sensitivity Level (MSL)

Module is qualified to Moisture Sensitivity Level (MSL) 3 in accordance with JEDEC J-STD-033. If the prescribed time limit is exceeded, users should bake module for 192 hours in drying equipment (<5% RH) at 40+5/-0 °C, or 8 hours at 120+5/-5 °C. Note that plastic tray is not heat-resistant, and only can be baked at 45° C.

Table 49: Moisture Sensitivity Level and Floor Life

Moisture Sensitivity Level (MSL)	Floor Life (out of bag) at factory ambient ≤30°C/60% RH or as stated
1	Unlimited at ≤30°C/85% RH
2	1 year
2a	4 weeks
3	168 hours
4	72 hours
5	48 hours
5a	24 hours
6	Mandatory bake before use. After bake, it must be reflowed within the time limit specified on the label.

**NOTE**

IPC / JEDEC J-STD-033 standard must be followed for production and storage.

## 6.5 Recommend Dimensions of SMT Stencil

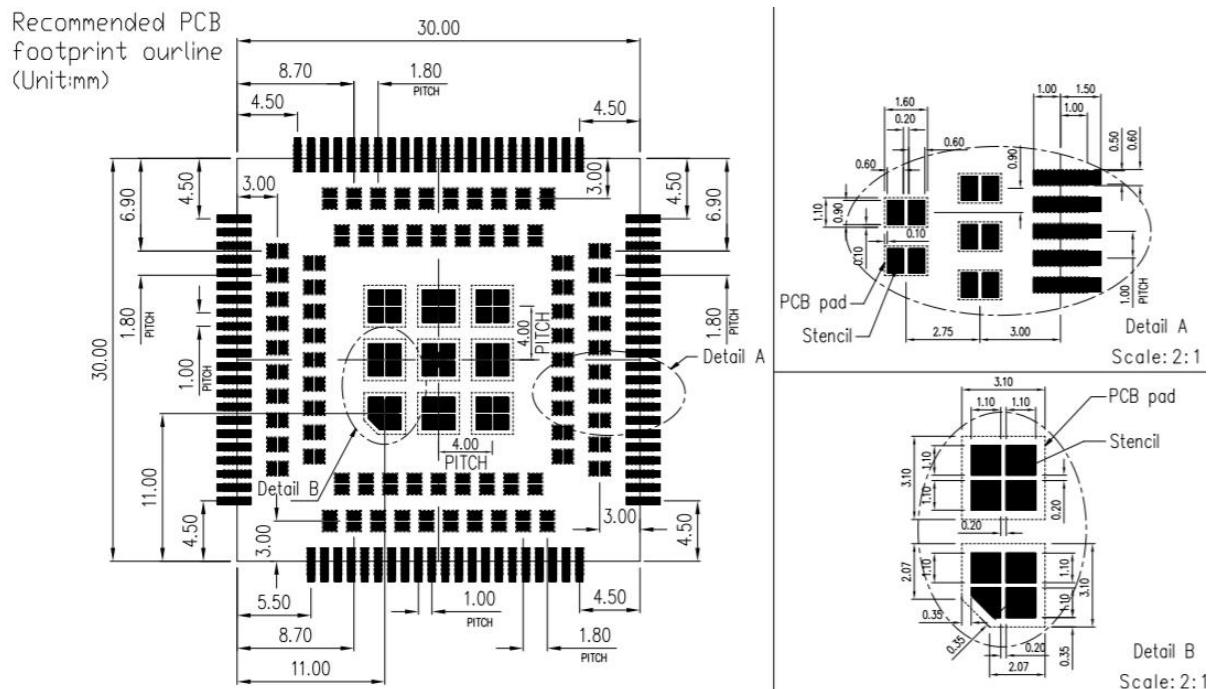


Figure 45: Recommend SMT Stencil

## 6.6 Stencil Foil Design Recommendation

The recommended thickness of stencil foil is more than 0.13mm.

## 7 Packaging

Module support tray packaging.

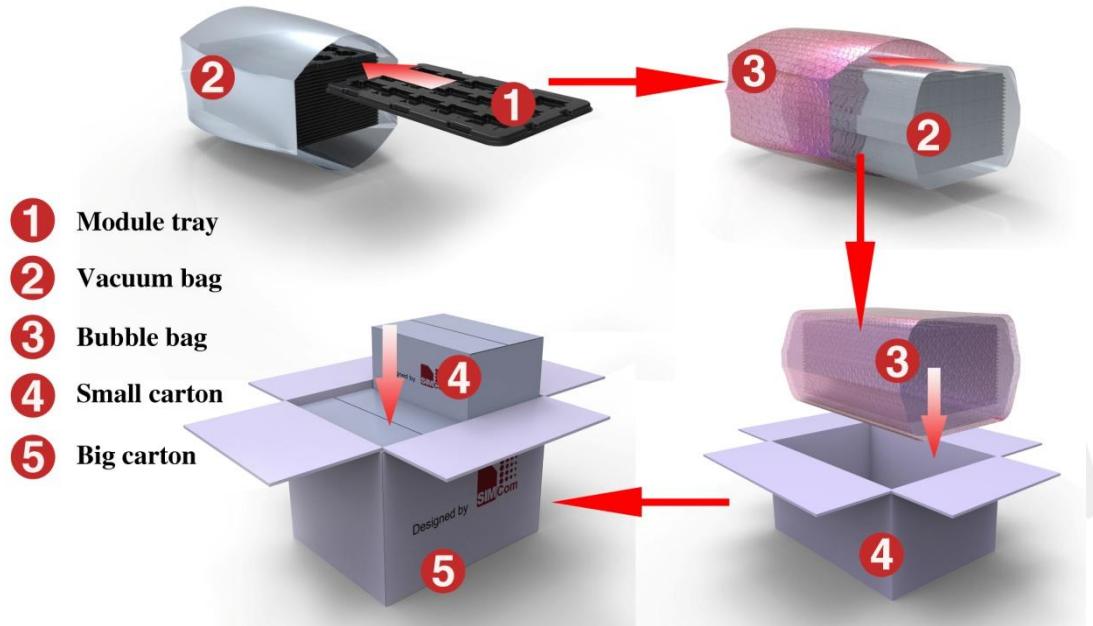


Figure 46: Packaging Diagram

Module tray drawing:

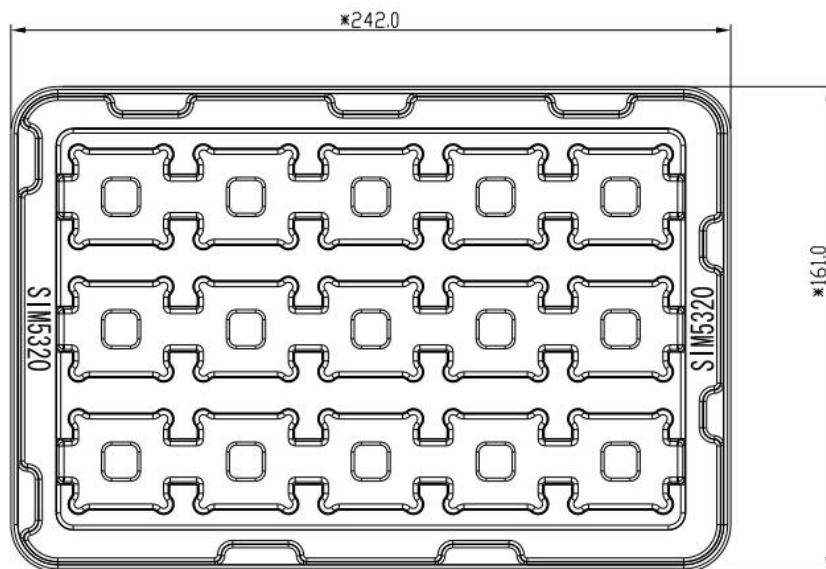


Figure 47: Tray Drawing

**Table 50: Tray Size**

Length ( ±3mm )	Width ( ±3mm )	Number
242.0	161.0	15

Small carton drawing:

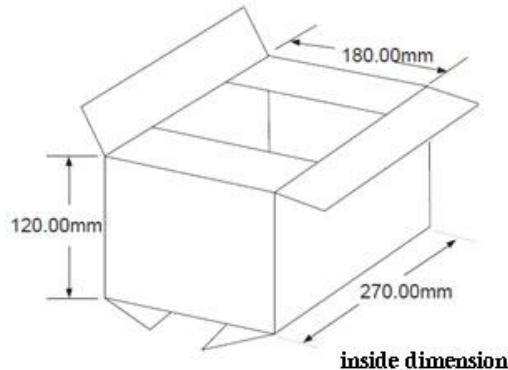


Figure 48: Small Carton Drawing

**Table 51: Small Carton Size**

Length ( ±10mm )	Width ( ±10mm )	Height ( ±10mm )	Number
270	180	120	15*20=300

Big carton drawing:

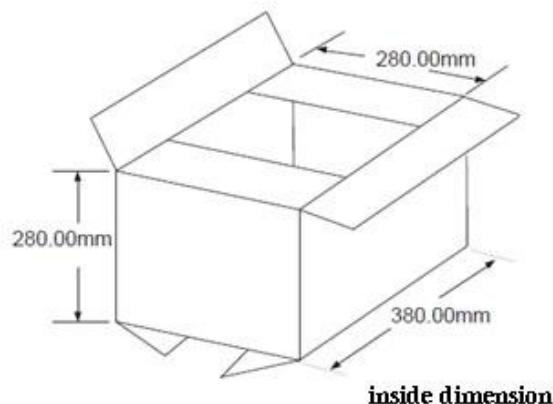


Figure 49: Big Carton Drawing

**Table 52: Big Carton Size**

Length ( ±10mm )	Width ( ±10mm )	Height ( ±10mm )	Number
380	280	280	300*4=1200

## 8 Appendix

### 8.1 Coding Schemes and Maximum Net Data Rates over Air Interface

Table 53: Coding Schemes and Maximum Net Data Rates over Air Interface

Multislot definition(GPRS/EDGE)				
Slot class	DL slot number	UL slot number	Active number	slot
1	1	1	2	
2	2	1	3	
3	2	2	3	
4	3	1	4	
5	2	2	4	
6	3	2	4	
7	3	3	4	
8	4	1	5	
9	3	2	5	
10	4	2	5	
11	4	3	5	
12	4	4	5	
GPRS coding scheme	Max data rate ( 4 slots )		Modulation type	
CS 1 = 9.05 kb/s / time slot	36.2 kb/s		GMSK	
CS 2 = 13.4 kb/s / time slot	53.6 kb/s		GMSK	
CS 3 = 15.6 kb/s / time slot	62.4 kb/s		GMSK	
CS 4 = 21.4 kb/s / time slot	85.6 kb/s		GMSK	
MCS 1 = 8.8 kb/s / time slot	35.2 kb/s		GMSK	
MCS 2 = 11.2 kb/s / time slot	44.8 kb/s		GMSK	
MCS 3 = 14.8 kb/s / time slot	59.2 kb/s		GMSK	
MCS 4 = 17.6 kb/s / time slot	70.4 kb/s		GMSK	
MCS 5 = 22.4 kb/s / time slot	89.6 kb/s		8PSK	
MCS 6 = 29.6 kb/s / time slot	118.4 kb/s		8PSK	
MCS 7 = 44.8 kb/s / time slot	179.2 kb/s		8PSK	
MCS 8 = 54.4 kb/s / time slot	217.6 kb/s		8PSK	
MCS 9 = 59.2 kb/s / time slot	236.8 kb/s		8PSK	
HSDPA device category	Max data rate ( peak )		Modulation type	
Category 1	1.2M bps		16QAM,QPSK	
Category 2	1.2M bps		16QAM,QPSK	
Category 3	1.8M bps		16QAM,QPSK	

Category 4	1.8 Mbps	16QAM,QPSK
Category 5	3.6 Mbps	16QAM,QPSK
Category 6	3.6 Mbps	16QAM,QPSK
Category 7	7.2 Mbps	16QAM,QPSK
Category 8	7.2 Mbps	16QAM,QPSK
Category 9	10.2 Mbps	16QAM,QPSK
Category 10	14.4 Mbps	16QAM,QPSK
Category 11	0.9 Mbps	QPSK
Category 12	1.8 Mbps	QPSK
Category 13	17.6 Mbps	64QAM
Category 14	21.1 Mbps	64QAM
Category 15	23.4 Mbps	16QAM
Category 16	28 Mbps	16QAM
Category 17	23.4 Mbps	64QAM
Category 18	28 Mbps	64QAM
Category 19	35.5 Mbps	64QAM
Category 20	42 Mbps	64QAM
Category 21	23.4 Mbps	16QAM
Category 22	28 Mbps	16QAM
Category 23	35.5 Mbps	64QAM
Category 24	42.2 Mbps	64QAM
HSUPA device category	Max data rate ( peak )	Modulation type
Category 1	0.96 Mbps	QPSK
Category 2	1.92 Mbps	QPSK
Category 3	1.92 Mbps	QPSK
Category 4	3.84 Mbps	QPSK
Category 5	3.84 Mbps	QPSK
Category 6	5.76 Mbps	QPSK
LTE-FDD device category (Downlink)	Max data rate ( peak )	Modulation type
Category 1	10 Mbps	QPSK/16QAM/64QA M
Category 2	50 Mbps	QPSK/16QAM/64QA M
Category 3	100 Mbps	QPSK/16QAM/64QA M
Category 4	150 Mbps	QPSK/16QAM/64QA M
LTE-FDD device category (Uplink)	Max data rate ( peak )	Modulation type
Category 1	5 Mbps	QPSK/16QAM
Category 2	25 Mbps	QPSK/16QAM
Category 3	50 Mbps	QPSK/16QAM
Category 4	50 Mbps	QPSK/16QAM

## 8.2 Related Documents

Table 54: Related Documents

NO	Title	Description
[1]	SIM7500_SIM7600 Series_AT Command Manual_V1.xx	AT Command Manual
[2]	ITU-T Draft new recommendationV.25ter	Serial asynchronous automatic dialing and control
[3]	GSM 07.07	Digital cellular telecommunications (Phase 2+); AT command set for GSM Mobile Equipment (ME)
[4]	GSM 07.10	Support GSM 07.10 multiplexing protocol
[5]	GSM 07.05	Digital cellular telecommunications (Phase 2+); Use of Data Terminal Equipment – Data Circuit terminating Equipment (DTE – DCE) interface for Short Message Service (SMS) and Cell Broadcast Service (CBS)
[6]	GSM 11.14	Digital cellular telecommunications system (Phase 2+); Specification of the SIM Application Toolkit for the Subscriber Identity Module – Mobile Equipment (SIM – ME) interface
[7]	GSM 11.11	Digital cellular telecommunications system (Phase 2+); Specification of the Subscriber Identity Module – Mobile Equipment (SIM – ME) interface
[8]	GSM 03.38	Digital cellular telecommunications system (Phase 2+); Alphabets and language-specific information
[9]	GSM 11.10	Digital cellular telecommunications system (Phase 2) ; Mobile Station (MS) conformance specification ; Part 1: Conformance specification
[10]	3GPP TS 51.010-1	Digital cellular telecommunications system (Release 5); Mobile Station (MS) conformance specification
[11]	3GPP TS 34.124	Electromagnetic Compatibility (EMC) for mobile terminals and ancillary equipment.
[12]	3GPP TS 34.121	Electromagnetic Compatibility (EMC) for mobile terminals and ancillary equipment.
[13]	3GPP TS 34.123-1	Technical Specification Group Radio Access Network; Terminal conformance specification; Radio transmission and reception (FDD)
[14]	3GPP TS 34.123-3	User Equipment (UE) conformance specification; Part 3: Abstract Test Suites.
[15]	EN 301 908-02 V2.2.1	Electromagnetic compatibility and Radio spectrum Matters (ERM); Base Stations (BS) and User Equipment (UE) for IMT-2000. Third Generation cellular networks; Part 2: Harmonized EN for IMT-2000, CDMA Direct Spread (UTRA FDD) (UE) covering essential requirements of article 3.2 of the R&TTE Directive
[16]	EN 301 489-24 V1.2.1	Electromagnetic compatibility and Radio Spectrum Matters (ERM); Electromagnetic Compatibility (EMC) standard for

		radio equipment and services; Part 24: Specific conditions for IMT-2000 CDMA Direct Spread (UTRA) for Mobile and portable (UE) radio and ancillary equipment
[17]	IEC/EN60950-1(2001)	Safety of information technology equipment (2000)
[18]	3GPP TS 51.010-1	Digital cellular telecommunications system (Release 5); Mobile Station (MS) conformance specification
[19]	GCF-CC V3.23.1	Global Certification Forum - Certification Criteria
[20]	2002/95/EC	Directive of the European Parliament and of the Council of 27 January 2003 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS)
[21]	Module secondary-SMT-UGD-V1.xx	Module secondary SMT Guidelines
[22]	SIM7X00 Series_UART_Application Note_V1.xx SIM7100_SIM7500_SIM7600 Series_USB AUDIO_Application Note_V1.xx	This document describes how to use UART interface of SIMCom modules.
[23]	SIM7X00 Series_GPS_Application Note_V1.xx	USB AUDIO Application Note
[24]	SIM7X00 Series_GPS_Application Note_V1.xx	GPS Application Note
[25]	Antenna design guidelines for diversity receiver system	Antenna design guidelines for diversity receiver system
[26]	SIM7100_SIM7500_SIM7600_Sleep Mode_Application Note_V1.xx	Sleep Mode Application Note
[27]	7600CE-LAN-Reference Design V1.0	HSIC Application Note

## 8.3 Terms and Abbreviations

Table 55: Terms and Abbreviations

Abbreviation	Description
ADC	Analog-to-Digital Converter
ARP	Antenna Reference Point
BER	Bit Error Rate
BTS	Base Transceiver Station
CS	Coding Scheme
CSD	Circuit Switched Data
CTS	Clear to Send
DAC	Digital-to-Analog Converter
DRX	Discontinuous Reception
DSP	Digital Signal Processor
DTE	Data Terminal Equipment (typically computer, terminal, printer)
DTR	Data Terminal Ready
DTX	Discontinuous Transmission
EFR	Enhanced Full Rate
EGSM	Enhanced GSM
EMC	Electromagnetic Compatibility
ESD	Electrostatic Discharge
ETS	European Telecommunication Standard
EVDO	Evolution Data Only
FCC	Federal Communications Commission (U.S.)
FD	SIM fix dialing phonebook
FDMA	Frequency Division Multiple Access
FR	Full Rate
GMSK	Gaussian Minimum Shift Keying
GNSS	Global Navigation Satellite System
GPRS	General Packet Radio Service
GPS	Global Positioning System
GSM	Global Standard for Mobile Communications
HR	Half Rate
HSPA	High Speed Packet Access
I2C	Inter-Integrated Circuit
IMEI	International Mobile Equipment Identity
LTE	Long Term Evolution
MO	Mobile Originated
MS	Mobile Station (GSM engine), also referred to as TE
MT	Mobile Terminated
NMEA	National Marine Electronics Association

PAP	Password Authentication Protocol
PBCCH	Packet Switched Broadcast Control Channel
PCB	Printed Circuit Board
PCS	Personal Communication System, also referred to as GSM 1900
RF	Radio Frequency
RMS	Root Mean Square (value)
RTC	Real Time Clock
SIM	Subscriber Identification Module
SMS	Short Message Service
SPI	serial peripheral interface
SMPS	Switched-mode power supply
TDMA	Time Division Multiple Access
TE	Terminal Equipment, also referred to as DTE
TX	Transmit Direction
UART	Universal Asynchronous Receiver & Transmitter
VSWR	Voltage Standing Wave Ratio
SM	SIM phonebook
NC	Not connect
EDGE	Enhanced data rates for GSM evolution
HSDPA	High Speed Downlink Packet Access
HSUPA	High Speed Uplink Packet Access
ZIF	Zero intermediate frequency
WCDMA	Wideband Code Division Multiple Access
VCTCXO	Voltage control temperature-compensated crystal oscillator
USIM	Universal subscriber identity module
UMTS	Universal mobile telecommunications system

## 8.4 Safety Caution

Table 56: Safety Caution

Marks	Requirements
	When in a hospital or other health care facility, observe the restrictions about the use of mobiles. Switch the cellular terminal or mobile off, medical equipment may be sensitive and not operate normally due to RF energy interference.
	Switch off the cellular terminal or mobile before boarding an aircraft. Make sure it is switched off. The operation of wireless appliances in an aircraft is forbidden to prevent interference with communication systems. Forgetting to think much of these instructions may impact the flight safety, or offend local legal action, or both.
	Do not operate the cellular terminal or mobile in the presence of flammable gases or fumes. Switch off the cellular terminal when you are near petrol stations, fuel depots, chemical plants or where blasting operations are in progress. Operation of any electrical equipment in potentially explosive atmospheres can constitute a safety hazard.
	Your cellular terminal or mobile receives and transmits radio frequency energy while switched on. RF interference can occur if it is used close to TV sets, radios, computers or other electric equipment.
	Road safety comes first! Do not use a hand-held cellular terminal or mobile when driving a vehicle, unless it is securely mounted in a holder for hands free operation. Before making a call with a hand-held terminal or mobile, park the vehicle.
	GSM cellular terminals or mobiles operate over radio frequency signals and cellular networks and cannot be guaranteed to connect in all conditions, especially with a mobile fee or an invalid SIM card. While you are in this condition and need emergent help, please remember to use emergency calls. In order to make or receive calls, the cellular terminal or mobile must be switched on and in a service area with adequate cellular signal strength. Some networks do not allow for emergency call if certain network services or phone features are in use (e.g. lock functions, fixed dialing etc.). You may have to deactivate those features before you can make an emergency call. Also, some networks require that a valid SIM card be properly inserted in the cellular terminal or mobile.